

R5431Vxxxxx SERIES

EA-228-111209

OUTLINE

The R5431Vxxxxx Series are high voltage CMOS-based protection ICs for over-charge/discharge of rechargeable three-cell/four-cell Lithium-ion (Li+) / Lithium polymer, further include a short circuit protection circuit for preventing large external short circuit current and the protection circuits against the excess discharge-current and excess charge current.

Each of these ICs is composed of eleven voltage detectors, a reference unit, a delay circuit, a short circuit protector, an oscillator, a counter, and a logic circuit. When the over-charge voltage threshold or excess-charge current threshold crosses the each detector threshold from a low value to a high value, the output of C_{OUT} pin switches to "L" level after internal fixed delay time. To release over-charge detector after detecting over-charge, the detector can be reset and the output of C_{OUT} becomes "H" when a kind of load is connected to V_{DD} after a charger is disconnected from the battery pack and the cell voltage becomes lower than over-charge detector threshold. In case that a charger is continuously connected to the battery pack, if the cell voltage becomes lower than the over-charge detector threshold, over-charge state is also released.

The output of D_{OUT} pin, the output of the over-discharge detector and the excess discharge-current detector, switches to "L" level after internally fixed delay time, when discharged voltage crosses the detector threshold from a high value to a value lower than V_{DET2}.

After detecting over-discharge voltage, when the cell voltage becomes higher than the released voltage from over-discharge, over-discharge state is released and the output of D_{OUT} becomes "L".

By setting DS pin voltage as same as the V_{DD}, the testing time of protection circuit board can be shortened. The delay time of the over-charge detector, over-discharge detector, and excess current detector can be reduced into approximately 1/50. The output type of C_{OUT} and D_{OUT} is CMOS.

FEATURES

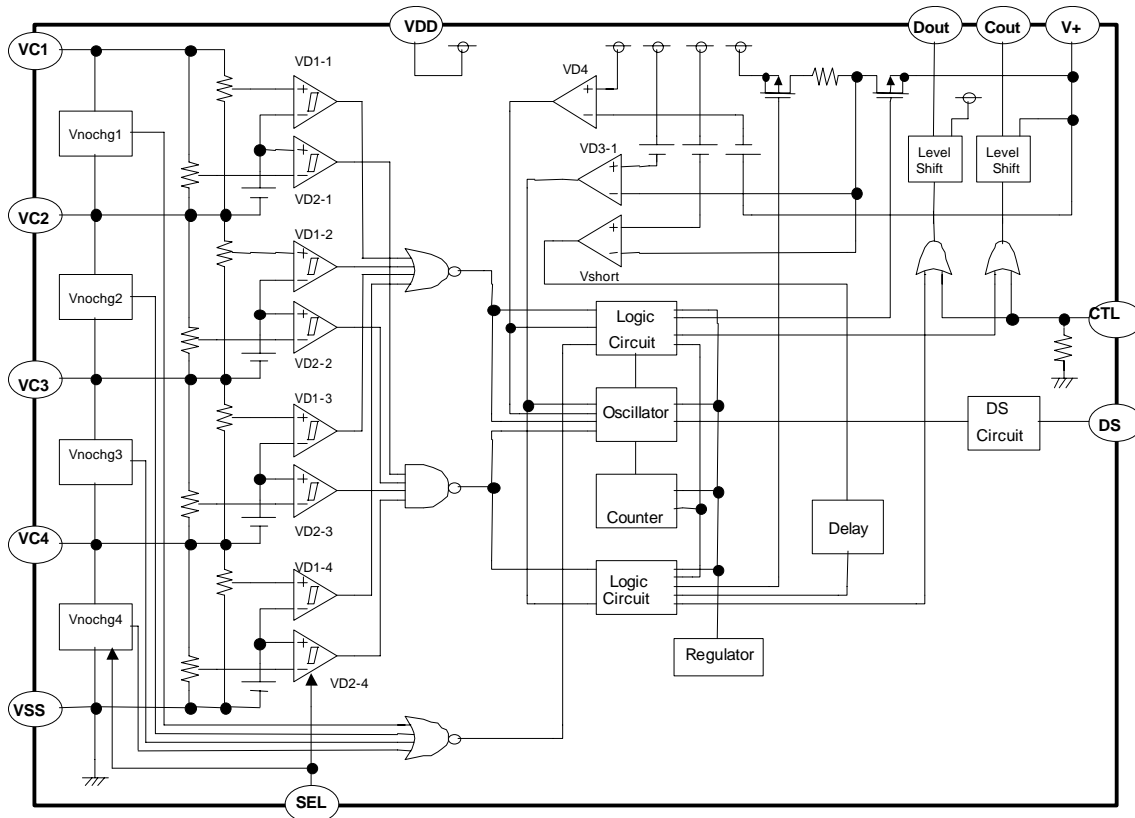
- Manufactured with High Voltage Tolerant Process ...Absolute Maximum Rating 30V
- Low supply currentSupply current (At normal mode) Typ. 12.0 μ A
 - Standby current Typ. 6.0 μ A
- High accuracy detector thresholdOver-charge detector (Ta=25°C) \pm 25mV
 - Over-discharge detector \pm 2.5%
 - Excess discharge-current detector \pm 20mV
 - Excess charge-current detector \pm 30mV
- Variety of detector threshold

Over-charge detector threshold	3.6V-4.5V step of 0.005V(VDET1n) (n=1,2,3,4)
Over-discharge detector threshold	2.0V-3.0V step of 0.005V(VDET2n) (n=1,2,3,4)
Excess discharge-current threshold1	VDD-0.20 V (Fixed)
Excess discharge-current threshold2	VDD-0.6V (Fixed)
Short detector threshold	VDD-1.2V (Fixed)
Excess charge-current threshold	VDD+0.2V (Fixed)
Over-charge released voltage	VDET1n-0.1V to 0.4V step of 0.05V (VREL1n) (n=1,2,3,4)
Over-discharge released voltage	VDET2n+(0.2V to 0.7V, step of 0.1V) (VREL2n) (n=1,2,3,4)
- Internal fixed Output delay timeOver-charge detector Output Delay 1.0s
 - Over-discharge detector Output Delay 1.2s/128ms
 - Excess discharge-current detector Output Delay 1 1.0s/12ms
 - Excess discharge-current detector Output Delay2 10ms/2ms
 - Excess charge-current detector Output Delay 8ms
 - Short Circuit detector Output Delay 300 μ s
- Output Delay Time Shortening Function..By forcing VDD voltage level to DS pin, the Output Delay time of detect and release the over-charge/discharge, the excess-charge/discharge current can be reduced.
If DS pin is not necessary, set the level to VSS. Especially, the Delay Time for over-charge/discharge, excess discharge current output delay 1 become about 1/50 of normal state.)
- 0V-battery charge.....For each cell, charge inhibit voltage is set at Max.=1.1V.
(Vnochgn, n=1,2,3,4)
- Small packageSSOP-16

APPLICATIONS

- Li+ / Li Polymer protector of over-charge, over-discharge, excess-current for battery pack
- Over-charge, discharge, and current protectors for notebook-PCs, power tools, and any other gadgets using on board Li+ / Li Polymer battery

BLOCK DIAGRAMS



SELECTION GUIDE

In the R5431Vxxxxx Series, input threshold of over-charge, over-discharge, excess charge/discharge current, and output delay time can be designated according to the application.

Part Number is designated as follows:

(ex.)

R5431V 301AA ←Part Number
 ↑ ↑ ↑ ↑
 a b c d

Code	Contents
a	Package Type V: SSOP-16
b	Serial Number for the R5431 Series designating input threshold for over-charge, over-discharge, excess charge/discharge-current detectors.
c	Designation of Output delay option
d	Designation of version symbols.

*Function Table

Code	Over-charge Released condition	Over-discharge Released condition	0V battery charge inhibit
R5431VxxxAA	By voltage	By voltage	inhibit
R5431VxxxBA	By voltage	By voltage	inhibit

Code	Over-charge detector output delay time tVdet1 (ms)	Over-discharge detector output delay time tVdet2 (ms)	Excess-discharge current detector threshold output delay time 1 tVdet3-1(ms)	Excess-discharge current detector threshold output delay time 2 tVdet3-2 (ms)	Excess-charge current detector threshold output delay time tVdet4 (ms)	Short detector threshold output delay time Tshort(μ s)
R5431VxxxAA	1000	1200	1000	10	8	300
R5431VxxxBA	1000	128	12	2	8	300

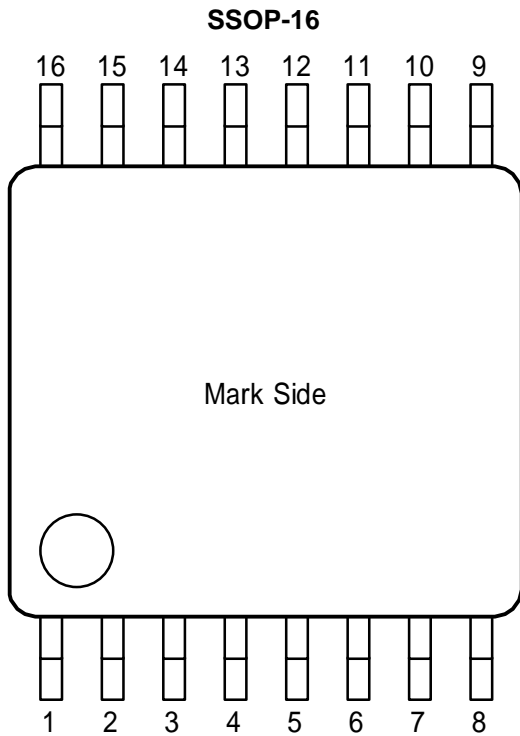
***Product name list**

Code	Over-charge detector threshold VDET1n (V) *1	Over-charge Released voltage VREL1n (V) *1	Over-discharge detector threshold VDET2n (V) *1	Over-discharge Released voltage VREL2n (V) *1	Excess-discharge Current detector threshold 1 VDET3-1 (V) *2	Excess-discharge current detector threshold 2 VDET3-2 (V) *2	Excess-charge current detector threshold VDET4 (V) *2
R5431V301AA	4.350	4.150	2.300	3.000	-0.200	-0.600	0.200
R5431V303AA	3.650	3.400	2.000	3.000	-0.200	-0.600	0.200
R5431V304AA	4.300	4.100	2.300	3.000	-0.200	-0.600	0.200
R5431V301BA	4.350	4.150	2.300	3.000	-0.200	-0.600	0.200
R5431V303BA	3.650	3.400	2.000	3.000	-0.200	-0.600	0.200
R5431V304BA	4.300	4.100	2.300	3.000	-0.200	-0.600	0.200
R5431V305BA	3.900	3.700	2.500	2.800	-0.200	-0.600	0.200
R5431V306BA	4.275	4.075	2.700	3.000	-0.200	-0.600	0.200
R5431V307BA	4.275	4.075	2.300	2.700	-0.200	-0.600	0.200

*1: n=1,2,3,4

*2: With reference to the V_{DD} level

PIN CONFIGURATIONS



PIN DESCRIPTION

Pin No.	Symbol	Description
1	C _{OUT}	Output pin of over-charge detection, CMOS output
2	V ₊	Charger positive terminal input pin
3	D _{OUT}	Output pin of over-discharge detection, CMOS output
4	NC	No Connection
5	NC	No Connection
6	DS	Output Delay Time Shortening Pin
7	V _{SS}	V _{SS} pin. Ground pin for the IC
8	NC	No Connection
9	NC	No Connection
10	SEL	3-cell/4-cell alternative pin
11	CTL	Charge/discharge FET control pin
12	VC ₄	Positive terminal Pin for Cell-4
13	VC ₃	Positive terminal Pin for Cell-3
14	VC ₂	Positive terminal pin for Cell-2
15	VC ₁	Positive terminal pin for Cell-1
16	VDD	VDD Pin

ABSOLUTE MAXIMUM RATINGS

Ta=25°C, Vss=0V

Symbol	Item	Ratings	Unit
V _{DD}	Supply voltage	-0.3 to 26	V
V _{C1}	Input Voltage Positive input pin for Cell-1	V _{C2} -0.3 to V _{C2} +6.5	V
V _{C2}	Positive input pin for Cell-2	V _{C3} -0.3 to V _{C3} +6.5	
V _{C3}	Positive input pin for Cell-3	V _{C4} -0.3 to V _{C4} +6.5	
V _{C4}	Positive input pin for Cell-4	V _{SS} -0.3 to V _{SS} +6.5	
V ₊	Charger positive input pin voltage	V _{SS} -0.3 to 30	
SEL	SEL pin voltage	V _{SS} -0.3 to V _{DD} +0.3	
CTL	CTL pin voltage	V _{SS} -0.3 to V _{DD} +0.3	
DS	DS pin voltage	V _{SS} -0.3 to V _{DD} +0.3	
V _{COUT}	Output voltage C _{OUT} pin	V _{SS} -0.3 to 30	V
V _{DOUT}	D _{OUT} pin	V _{SS} -0.3 to V _{DD} +0.3	V
P _D	Power dissipation	685	mW
T _a	Operating temperature range	-40 to 85	°C
T _{stg}	Storage temperature range	-55 to 125	°C

ELECTRICAL CHARACTERISTICS

R5431V3XXAA

Unless otherwise specified, Ta=25°C

Symbol	Item	Conditions	Min.	Typ.	Max.	Unit
V _{DD1}	Operating input voltage	Voltage defined as V _{DD} -V _{SS}	2		20	V
V _{nochg}	Maximum charge inhibit Voltage (n=1,2,3,4)	V _{DD} =V _{C1} V _{DD} =V ₊			1.100	V
V _{DET1n}	CELLn Over-charge threshold (n=1,2,3,4)	Detect rising edge of supply voltage R _n =330Ω	V _{DET1n} -0.025	V _{DET1n}	V _{DET1n} +0.025	V
V _{REL1n}	CELLn Over-charge released voltage	R _n =330Ω	V _{REL1n} -0.050	V _{REL1n}	V _{REL1n} +0.050	V
t _{VDET1}	Output delay of over-charge	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V _{CELL1} =3.5V to 4.5V (n=2,3,4)	0.7	1.0	1.3	s
t _{VREL1}	Output delay of release from over-charge	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V _{CELL1} =4.5V to 3.5V (n=2,3,4)	11	16	21	ms
V _{DET2n}	CELLn Over-discharge threshold (n=1,2,3,4)	Detect falling edge of supply voltage	V _{DET2n} ×0.975	V _{DET2n}	V _{DET2n} ×1.025	V
V _{REL2n}	CELLn Released Voltage from Over-discharge (n=1,2,3,4)	Detect rising edge of supply voltage	V _{REL2n} ×0.975	V _{REL2n}	V _{REL2n} ×1.025	V
t _{VDET2}	Output delay of over-discharge	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V _{CELL1} =3.5V to 2.0V (n=2,3,4)	0.8	1.2	1.6	s
t _{VREL2}	Output delay of release from over-discharge	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V _{CELL1} =2.0V to 3.5V, (n=2,3,4)	0.7	1.2	1.7	ms
V _{DET3-1}	Excess discharge-current threshold 1	Detect falling edge, V _{DD} pin voltage base	V _{DET3-1} -0.020	V _{DET3-1}	V _{DET3-1} +0.020	V
V _{DET3-2}	Excess discharge-current threshold 2	Detect falling edge, V _{DD} pin voltage base	-0.700	-0.600	-0.500	V
t _{VDET3-1}	Output delay of excess discharge current 1	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V ₊ =V _{DD} to V _{DET3-1} -0.1V, (n=1,2,3,4)	0.7	1.0	1.3	s
t _{VDET3-2}	Output delay of excess discharge current 2	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V ₊ =V _{DD} to V _{DET3-2} -0.2V, (n=1,2,3,4)	7	10	13	ms
t _{VREL3}	Output delay of release from excess discharge-current	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V ₊ =V _{DET3-2} -0.1V to V _{DD} (n=1,2,3,4)	0.7	1.2	1.7	ms
V _{DET4}	Excess charge-current threshold	V _{DD} =V _{C1} , V _{CELLn} =3.5V (n=1,2,3,4) Detect rising edge, the value is V _{DD} base.	0.17	0.20	0.23	V
t _{VDET4}	Output delay of excess charge-current	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V ₊ =V _{DD} to V _{DD} +0.5V, (n=1,2,3,4) V _{DD} base	5	8	11	ms
t _{VREL4}	Output delay of release from excess charge-current	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V ₊ =V _{DD} +0.5V to V _{DD} (n=1,2,3,4)	0.7	1.2	1.7	ms
V _{short}	Short protection voltage	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V _{DD} base (n=1,2,3,4)	-1.7	-1.2	-0.7	V
t _{short}	Output Delay of Short protection	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V ₊ =V _{DD} to V _{DD} +0.5V, (n=1,2,3,4)	200	300	500	μs
R _{short}	Reset resistance for Excess Discharge current protection	V _{DD} =14.4V, V ₊ =V _{DD} -1V	15	30	65	kΩ
I _{SS}	Supply current	V _{DD} =V _{C1} , V _{CELLn} =3.9V (n=1,2,3,4)		12	30	μA
I _{stb}	Standby current	V _{DD} =V _{C1} , V _{CELLn} =2.0V (n=1,2,3,4)		6	12	μA

*Note: V_{CELLn} means Cell-n's voltage. n=1,2,3,4

R5431V3XXBA version

Unless otherwise specified, Ta=25°C

Symbol	Item	Conditions	Min.	Typ.	Max.	Unit
V _{DD1}	Operating input voltage	Voltage defined as V _{DD} -V _{SS}	2		20	V
V _{noc hgn}	Maximum charge inhibit Voltage (n=1,2,3,4)	V _{DD} =V _{C1} V _{DD} =V+			1.100	V
V _{DET1n}	CELLn Over-charge threshold (n=1,2,3,4)	Detect rising edge of supply voltage Rn=330Ω	V _{DET1n} -0.025	V _{DET1n}	V _{DET1n} +0.025	V
V _{REL1n}	CELLn Over-charge released voltage	Rn=330Ω	V _{REL1n} -0.050	V _{REL1U}	V _{REL1n} +0.050	V
t _{VDET1}	Output delay of over-charge	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V _{CELL1} =3.5V to 4.5V (n=2,3,4)	0.7	1.0	1.3	s
t _{VREL1}	Output delay of release from over-charge	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V _{CELL1} =4.5V to 3.5V (n=2,3,4)	11	16	21	ms
V _{DET2n}	CELLn Over-discharge threshold (n=1,2,3,4)	Detect falling edge of supply voltage	V _{DET2n} ×0.975	V _{DET2n}	V _{DET2n} ×1.025	V
V _{REL2n}	CELLn Released Voltage from Over-discharge (n=1,2,3,4)	Detect rising edge of supply voltage	V _{REL2n} ×0.975	V _{REL2n}	V _{REL2n} ×1.025	V
t _{VDET2}	Output delay of over-discharge	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V _{CELL1} =3.5V to 2.0V (n=2,3,4)	89	128	167	ms
t _{VREL2}	Output delay of release from over-discharge	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V _{CELL1} =2.0V to 3.5V, (n=2,3,4)	0.7	1.2	1.7	ms
V _{DET3-1}	Excess discharge-current threshold 1	Detect falling edge, VDD voltage base	V _{DET3-1} -0.020	V _{DET3-1}	V _{DET3-1} +0.020	V
V _{DET3-2}	Excess discharge-current threshold 2	Detect falling edge, VDD voltage base	-0.700	-0.600	-0.500	V
t _{VDET3-1}	Output delay of excess discharge current 1	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V+=V _{DD} to V _{DET3-1} -0.1V, (n=1,2,3,4)	8	12	16	ms
t _{VDET3-2}	Output delay of excess discharge current 2	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V+=V _{DD} to V _{DET3-2} -0.2V, (n=1,2,3,4)	1.4	2.0	2.6	ms
t _{VREL3}	Output delay of release from excess discharge-current	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V+=V _{DET3-2} -0.1V to V _{DD} (n=1,2,3,4)	0.7	1.2	1.7	ms
V _{DET4}	Excess charge-current threshold	V _{DD} =V _{C1} , V _{CELLn} =3.5V (n=1,2,3,4) Detect rising edge, the value is V _{DD} base.	0.17	0.20	0.23	V
t _{VDET4}	Output delay of excess charge-current	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V+=V _{DD} to V _{DD} +0.5V, (n=1,2,3,4) V _{DD} base	5	8	11	ms
t _{VREL4}	Output delay of release from excess charge-current	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V+=V _{DD} +0.5V to V _{DD} (n=1,2,3,4)	0.7	1.2	1.7	ms
V _{short}	Short protection voltage	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V _{DD} base (n=1,2,3,4)	-1.7	-1.2	-0.7	V
t _{short}	Output Delay of Short protection	V _{DD} =V _{C1} , V _{CELLn} =3.5V, V+=V _{DD} to V _{DD} +0.5V, (n=1,2,3,4)	200	300	500	μs
R _{short}	Reset resistance for Excess Discharge current protection	V _{DD} =14.4V, V+=V _{DD} -1V	15	30	65	kΩ
I _{SS}	Supply current	V _{DD} =V _{C1} , V _{CELLn} =3.9V (n=1,2,3,4)		12	30	μA
I _{Stb}	Standby current	V _{DD} =V _{C1} , V _{CELLn} =2.0V (n=1,2,3,4)		6	12	μA

*Note: V_{CELLn} means Cell-n's voltage. n=1,2,3,4

R5431Vxxxxx

Input/ Output Pins (R5431V3XXAA/BA common)

Unless otherwise specified, Ta=25°C

Symbol	Item	Conditions	Min.	Typ.	Max.	Unit
V _{IH1}	SEL pin "H" input voltage		V _{DD} x 0.8		V _{DD} +0.3	V
V _{IL1}	SEL pin "L" input voltage		V _{SS} -0.3		V _{DD} x 0.2	V
V _{IH2}	CTL pin "H" input voltage		V _{DD} x 0.8		V _{DD} +0.3	V
V _{IL2}	CTL pin "L" input voltage		V _{SS} -0.3		V _{DD} x 0.2	V
V _{IH3}	DS pin "H" input voltage		V _{DD} x 0.8		V _{DD} +0.3	V
V _{IL3}	DS pin "L" input voltage		V _{SS} -0.3		V _{DD} x 0.2	ms
V _{OL1}	C _{OUT} Nch ON voltage	I _{OL} =50μA, V _{DD} =V _{C1} , V _{celln} =3.5V (n=1,2,3,4), CTL=V _{SS}		0.1	0.5	V
V _{OH1}	C _{OUT} Pch ON voltage	I _{OH} =-50μA, V _{DD} =V _{C1} , V _{celln} =3.5V (n=1,2,3,4), CTL=V _{DD}	13.5	13.9		V
V _{OL2}	D _{OUT} Nch ON voltage	I _{OL} =50μA, V _{DD} =V _{C1} , V _{celln} =3.5V (n=1,2,3,4), CTL=V _{SS}		0.1	0.5	V
V _{OH2}	D _{OUT} Pch ON voltage	I _{OH} =-50μA, V _{DD} =V _{C1} , V _{celln} =3.5V (n=1,2,3,4), CTL=V _{DD}	13.5	13.9		V
I _{IH}	CTL pin "H" input current	V _{DD} =V _{C1} , V _{CELLn} =3.5V, (n=1,2,3,4), CTL=14V	0.15	0.70	1.60	μA

OPERATION

- **VDET1n / Over-Charge Detectors (n=1, 2, 3, 4)**

While the cell is charged, the voltage between VC1 pin and VC2 pin (the voltage of the Cell-1), the voltage between VC2 pin and VC3 pin (the voltage of the Cell-2), the voltage between VC3 pin and VC4 pin (the voltage of the Cell-3), the voltage of VC4 pin and VSS pin (the voltage of Cell-4) are supervised. Even if one of the cells' voltage becomes equal or more than the over-charge detector threshold, the over-charge is detected, and an external charge control Pch MOSFET turns off with C_{OUT} pin being at "H" level.

To reset the over-charge and make the C_{OUT} pin level to "L" again after detecting over-charge, in such conditions that a time when the all Cells' voltages are down to a level lower than over-charge voltage, by connecting a kind of load to V_{DD} after disconnecting a charger from the battery pack. Then, the output voltage of C_{OUT} pin becomes "L", and it makes an external Pch MOSFET turn on, and charge cycle is available. If a charger is continuously connected to the battery pack, when all the cells voltages are lower than the released voltage from over-charge, charge cycle is acceptable. Thus, this over-charge detector has hysteresis. To judge whether or not load is connected, the built-in excess-discharge current detector is used. By connecting some load, V₊ pin voltage becomes equal or less than excess-discharge current detector threshold, and reset the over-charge detecting state.

Further, even if when one of the cells is equal or higher than the over-charge detector threshold, if a charger is removed and some load is connected, C_{OUT} outputs "H", however, load current can flow through the parasitic diode of the external charge control Pch MOSFET. After that, when the V_{DD} pin voltage becomes lower than the over-charge detector threshold, C_{OUT} becomes "L".

Internal fixed output delay times for over-charge detection and release from over-charge exist. Even if one of voltage of Cells keeps its level more than the over-charge detector threshold, and output delay time passes, over-charge voltage is detected. Even when the voltage of each cell becomes equal or higher level than V_{DET1} if these voltages would be back to a level lower than the over-charge detector threshold within a time period of the output delay time, the over-charge is not detected. Besides, after detecting over-charge, each Cell voltage is lower than the over-charge detector threshold, even if a charger is removed and a load is connected, if the voltage is recovered within output delay time of release from over-charge, over-charge state is not released.

A level shifter incorporated in a buffer driver for the C_{OUT} pin makes the "H" level of C_{OUT} pin to the V₊ pin voltage.

The output of the C_{OUT} pin is V_{SS} and V₊ with CMOS buffer.

- **VDET2n / Over-Discharge Detectors (n=1, 2, 3, 4)**

While the cells are discharged, the voltage between VC1 pin and VC2 pin (the voltage of Cell1), the

voltage between VC2 pin and VC3 pin (Cell2 voltage), the voltage between VC3 pin and VC4 pin (Cell3 voltage) , and the voltage between VC4 pin and Vss pin (Cell4 voltage) are supervised. Even if one of the cells' voltage becomes equal or less than the over-discharge detector threshold, the over-discharge is detected and discharge stops by the external discharge control Pch MOSFET turning off with the D_{OUT} pin being at "H" level.

The condition to release over-discharge voltage detector is that connecting a charger to the battery after detecting over-discharge voltage, and when the cell voltage becomes lower than over-discharge detector threshold, some charge current flows through the parasitic diode of an external Pch MOSFET, and when each cell voltage is higher than the released voltage from over-discharge, D_{OUT} pin becomes "L" level, and by turning on the external Pch MOSFET, discharge becomes possible. When a charger is connected to the battery, if each cell is more than the released voltage from over-discharge, after the delay time of the released from over-discharge, D_{OUT} pin becomes "L". Thus, the over-discharge detector has hysteresis.

The output delay time for over-discharge detect is fixed internally. Even if one of the voltage of Cells is down to equal or lower than the over-discharge detector threshold, if the voltage of each Cell would be back to a level higher than the over-discharge detector threshold within a time period of the output delay time, the over-discharge is not detected. Output delay time for release from over-discharge is also set.

After detecting over-discharge, supply current would be reduced and be into standby by halting unnecessary circuits and consumption current of the IC itself is made as small as possible.

When a cell voltage equals to zero, if the voltage of each cell is lower than charge inhibit maximum voltage, charge is not acceptable. All the cell voltages are higher than charge inhibit maximum voltage, C_{OUT} pin becomes "L" and a system is allowable to charge.

The output type of D_{OUT} pin is CMOS having "H" level of V_{DD} and "L" level of V_{SS}.

- **VDET3-n (n=1, 2) /Excess discharge-current Detector, Short Circuit Protector**

When the charge and discharge is acceptable, V₊ pin voltage is supervised, if the load is short and V₊ pin voltage becomes equal or lower than excess discharge current threshold, and equal or more than short detector threshold, the status becomes excess discharge current detected condition. If V₊ pin voltage becomes equal or lower than short circuit detector threshold, the status becomes short circuit detected, then D_{OUT} pin outputs "H" and by turning off the external Pch MOSFET, large current flow is prevented. As for version A, excess discharge current detector has two thresholds, and each threshold has the output delay time. In terms of the output delay times, the delay time for the excess discharge current detector 2 is set shorter than excess discharge current 1.

The output delay times for the excess discharge-current detectors are internally fixed.

A quick recovery of V+ pin level from a value between Excess discharge current detector and short circuit detector threshold within the delay time, may keep the status as before excess discharge current detected. Output delay time for Release from excess discharge-current detection is also set.

When the short circuit protector is enabled, the delay time is also set.

The V + pin has a built-in pull-down resistor to the Vss pin, that is, the resistance to release from excess-discharge current.

After an excess discharge-current or short circuit protection is detected, removing a cause of excess discharge-current or external short circuit and opened, V+ pin level is going to the VDD pin level, through the built-in pulled down resistor. When the V+ pin becomes equal or more than excess discharge current detector threshold, the excess-discharge current or short circuit status is automatically released. The reset resistor of excess discharge-current is off at normal state. Only when detecting excess discharge-current or short circuit, the resistor is on.

Output delay time of excess discharge-current is set shorter than the delay time for over-discharge detector. Therefore, if VDD voltage would be lower than V_{DET2n} at the same time as the excess discharge-current is detected, the R5431Vxxxxx is at excess discharge-current detection mode. By disconnecting a load and opened, the excess discharge current status is automatically released.

- **VDET4/ Excess charge-current detector**

When the battery pack is chargeable and discharge is also possible, VDET4 senses V+ pin voltage. For example, in case that a battery pack is charged by an inappropriate charger, an excess current flows, then the voltage of V+ pin becomes equal or more than excess charge-current detector threshold, then the output of COUT becomes "H", and prevents from flowing excess current in the circuit by turning off the external Pch MOSFET.

Output delay of excess charge current is internally fixed. Even the voltage level of V+ pin becomes equal or lower than the excess charge-current detector threshold, if the voltage becomes lower than excess charge current threshold within the delay time, the excess charge current is not detected. Output delay for the release from excess charge current is also set.

VDET4 can be released with disconnecting a charger and connecting a load.

- **DS (Delay Shorten) function**

Output delay time of over-charge, over-discharge, excess discharge current, excess charge current and release from those detecting modes can be shorter than those setting value by forcing VDD voltage level to DS pin.

- **Operation against cell Unbalance**

If one of the cells detects over-charge and the output of COUT becomes "H", even if the other cell detects over-discharge, the over-charge status is maintained and the output of COUT keeps "H". If one of the cell detects over-charge and the output of COUT becomes "H", the other cell detects

over-discharge and the former cell is released from over-charge, after the delay time of the released from over-charge, the output of COUT becomes "L", and after the delay time of detecting over-discharge, the output of DOUT becomes "H". After detecting over-discharge, internal unnecessary circuits are halted and the R5431V is into the standby mode. (Supply current Typ. 6.0 μ A)

- **Charge inhibit detector Vnochg-n (n=1, 2, 3, 4)**

Charge inhibit detector is equipped for each cell. Even if one of the cells' voltage is equal or lower than charge inhibit voltage, when a charger is connected, charge inhibit is detected, the output of COUT becomes "H", then by turning off the external Pch MOSFET, the charge is halted.

While the charge inhibit status, the cell voltage with equal or lower than the charge inhibit voltage is equal or lower than over-discharge voltage, both of the outputs of COUT and DOUT become "H" and the external MOSFETS become "off"/"off". Other than charge inhibit status, external MOSFETS will never be "off"/"off".

- **CTL pin**

By forcing VDD voltage level to CTL pin, the outputs of COUT and DOUT are set "H" compulsory.

CTL pin input and outputs of COUT and DOUT

CTL pin input	C _{OUT} output	D _{OUT} output
High	High	High
Open	normal	normal
Low	normal	normal

- **SEL pin**

SEL pin is used as switch over 3-cell protector and 4-cell protector. By forcing VSS voltage level to SEL pin, the operation of 4th cell's protection circuit, the signal is shut down, therefore, even if the 4th cell is shortened, over-discharge is not detected and operates as a 3-cell protector IC.

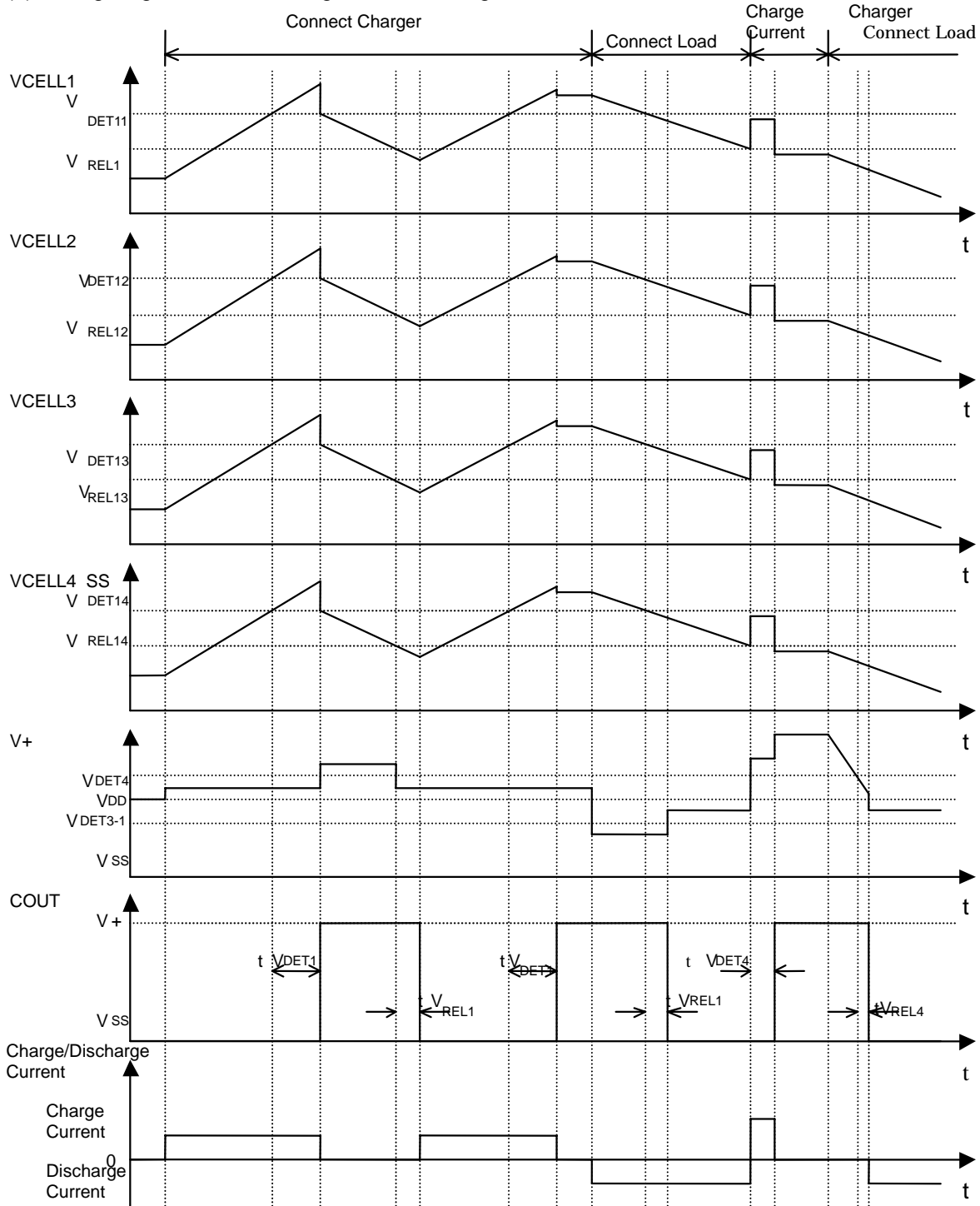
SEL pin must be set as V_{DD} voltage or V_{SS} voltage level.

SEL pin input and operation mode

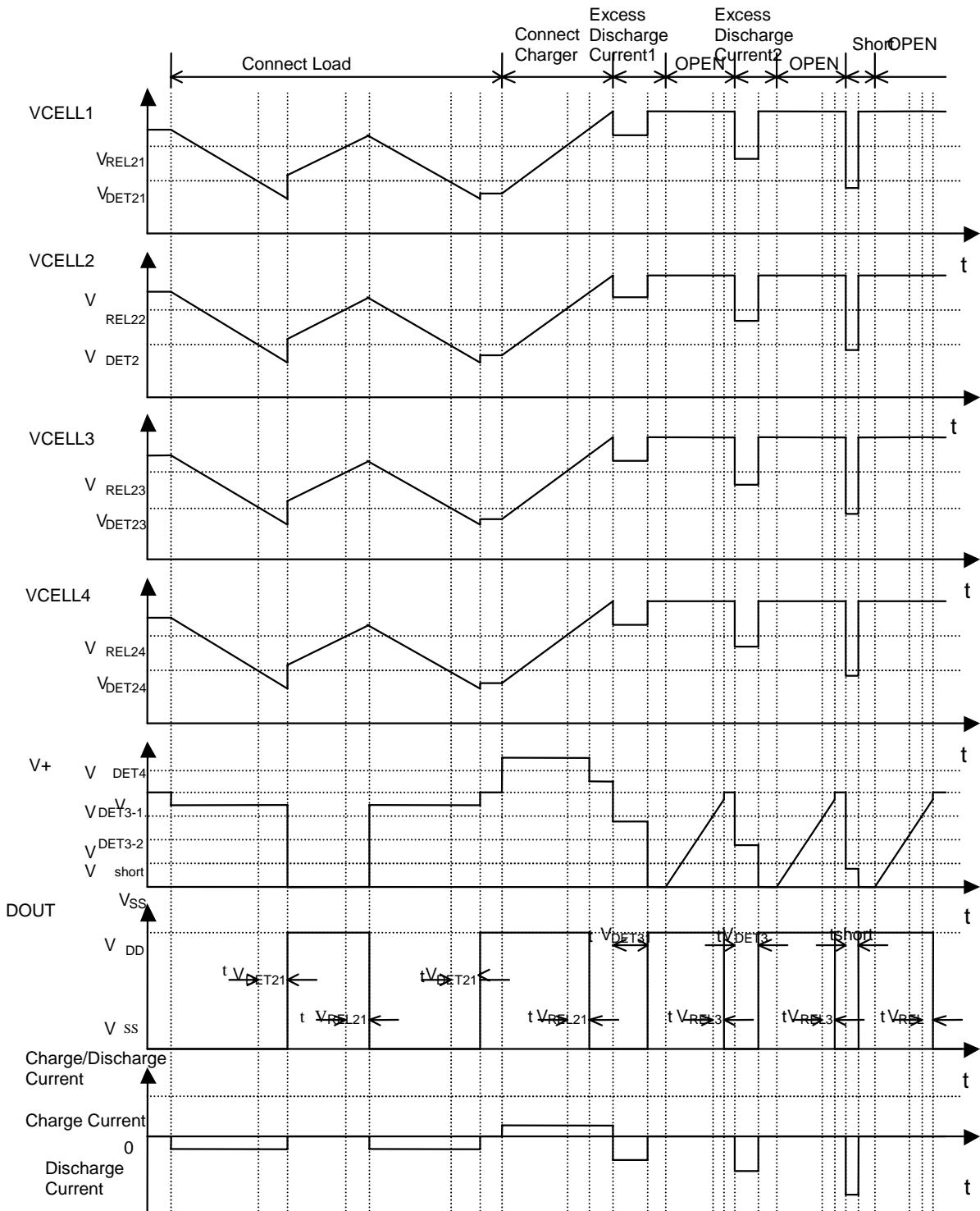
SEL pin input	Operation Mode
High	4-cell protector
Open	Indefinite
Low	3-cell protector

TIMING CHART

(1) Timing diagram of Over-charge, Excess charge current

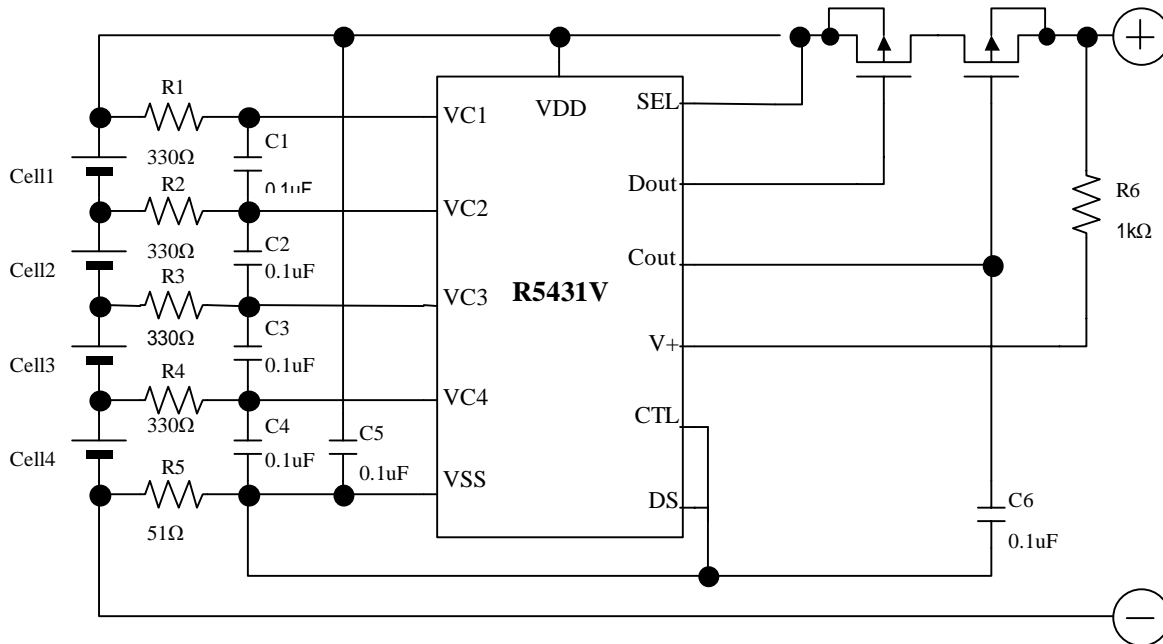


(2) Over-discharge, Excess discharge current 1, 2, Short circuit

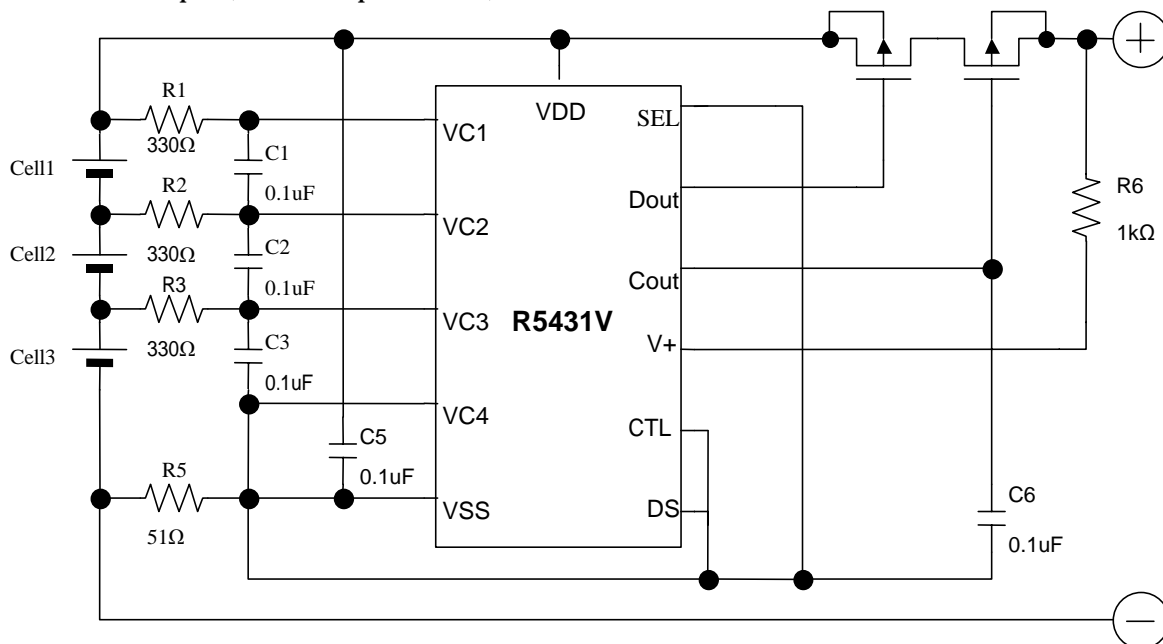


TYPICAL APPLICATION AND TECHNICAL NOTES

*Circuit example (for 4-cell protection)

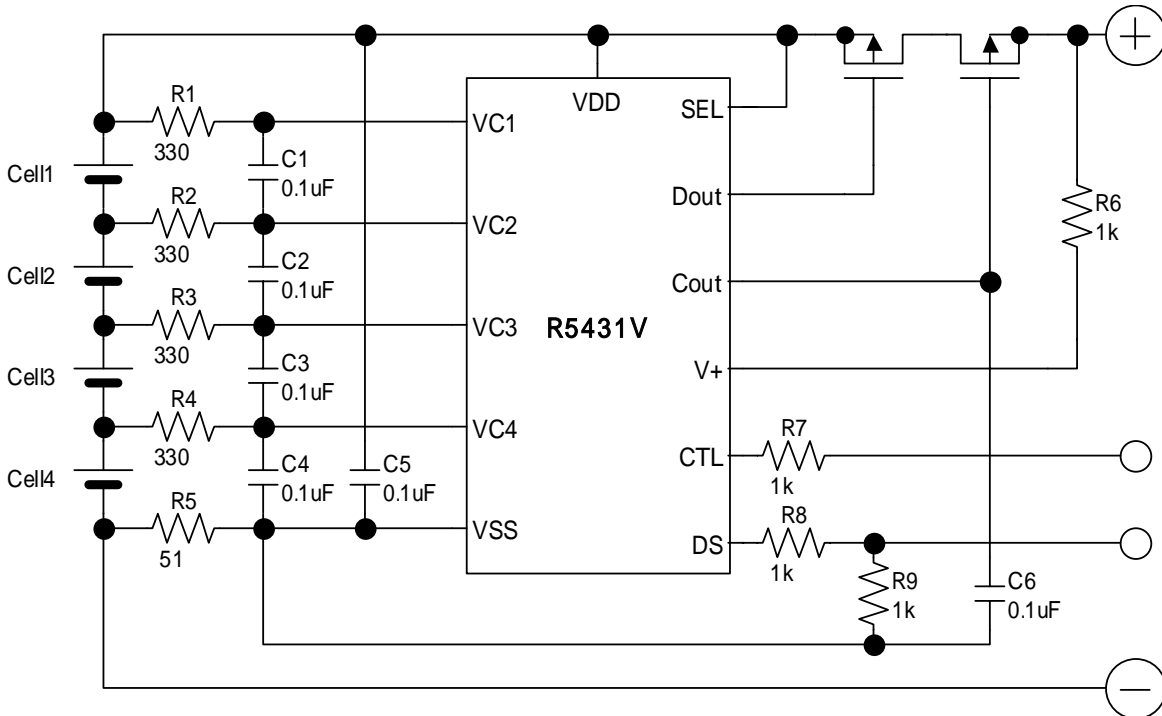


* Circuit example (for 3-cell protection)

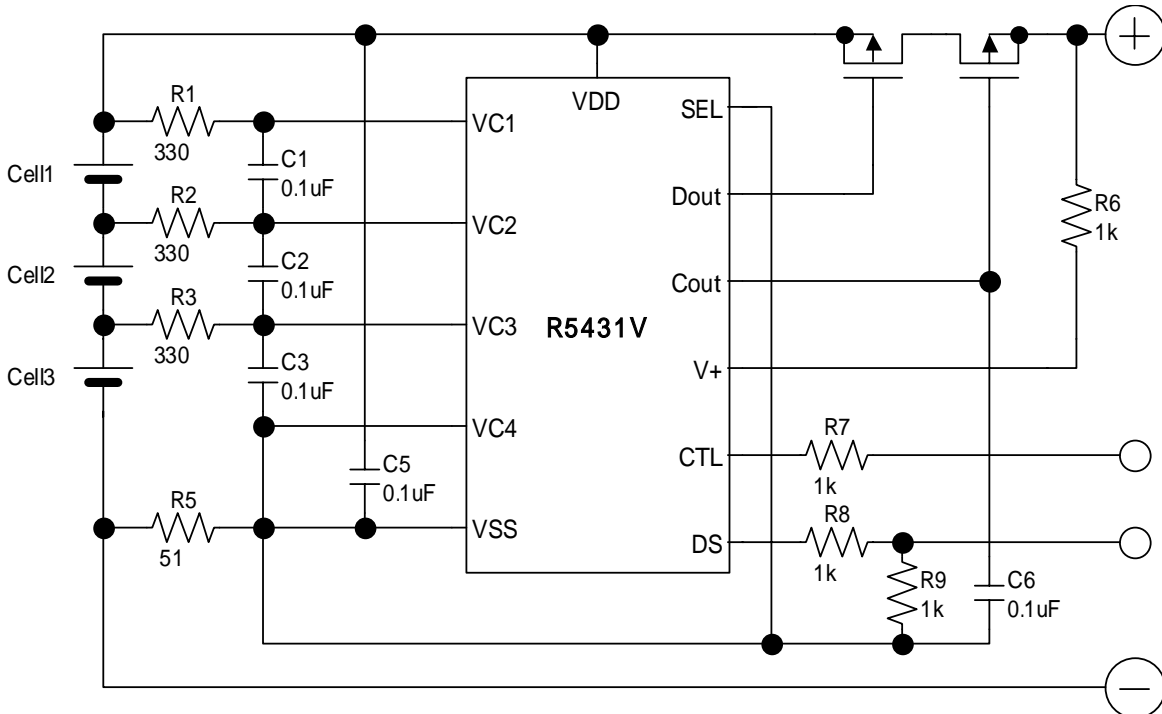


R5431Vxxxxx

*Circuit example (for 4-cell protection with CTL function and DS function)



*Circuit example (for 3-cell protection with CTL function and DS function)



TECHNICAL NOTES

R1, R2, R3, R4, R5, C1, C2, C3, C4, and C5 stabilize the supply voltage to the R5431Vxxxxx. If R1, R2, R3, R4, and R5 values are large, the conduction current inside the IC at detection mode, the detector threshold may rise, therefore recommended R1, R2, R3, R4 value is equal or less than 1k Ω . The recommended R5 value is equal or less than 330 Ω .

To stabilize the operation, the value of C1, C2, C3, C4, and C5 should be equal or more than 0.01 μ F.

R5 and R6 can operate also as parts for current limit circuit against the reverse charge or applying a charger with excess charging voltage beyond the absolute maximum rating of the R5431Vxxxxx. Small value of R5 and R6 may cause over-power consumption rating of the power dissipation of the R5431Vxxxxx. Thus, the total value of 'R5+R6' should be equal or more than 1k Ω .

If R5 value is set too large, by the conduction current inside the IC at detection, the detector threshold becomes lower, thus recommended R5 value is equal or more than 330 Ω . If R6 value is set too large, release operation by connecting a charger may be impossible, our recommendation value as R6 is equal or less than 10k Ω .

R7 and R8 can operate as parts for current limit circuit against forcing over voltage. If CTL function or CTL function is necessary, attach R7 and R8 with the resistance of 1k Ω or more. Since a pull-down resistor is not built in the DS pin, when the DS function is necessary, attach R9 with the resistance of 1k Ω .

To stabilize the operation of the IC, use a capacitor with a range of the capacity from 0.06 μ F to 0.1 μ F as C6.

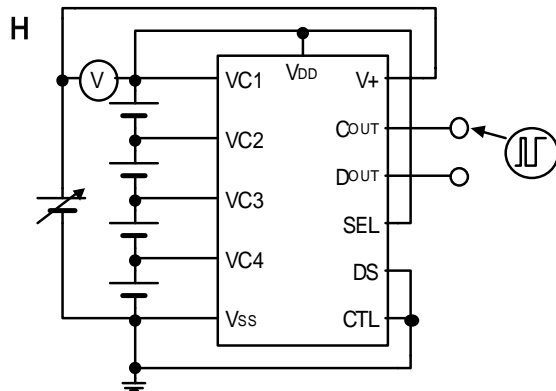
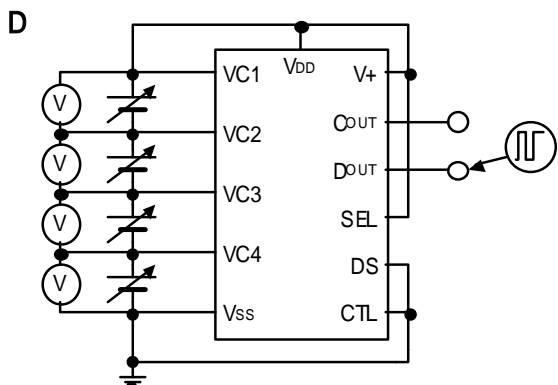
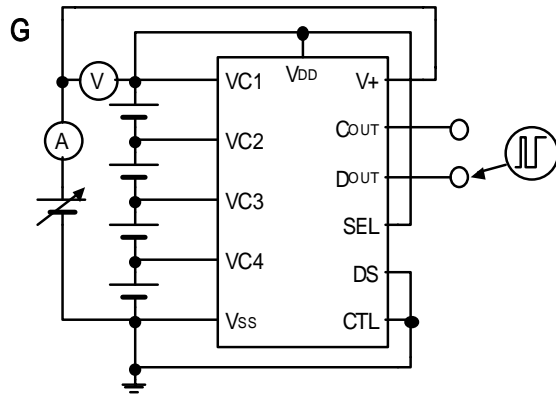
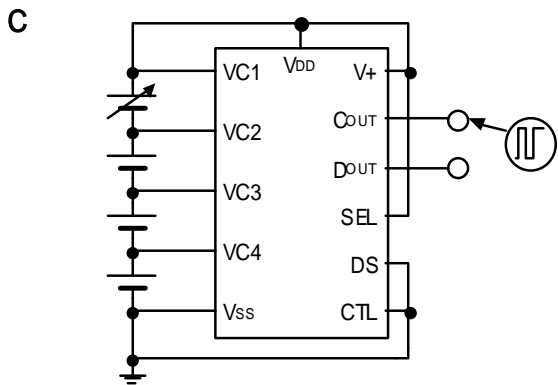
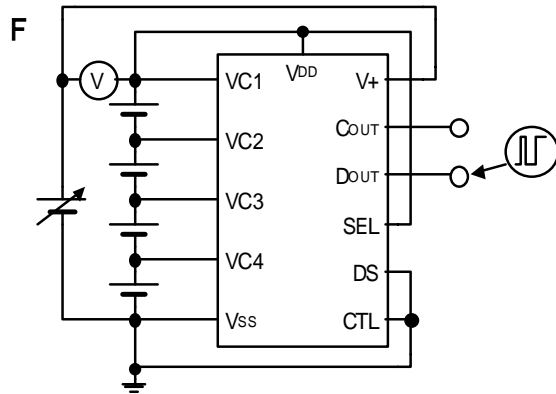
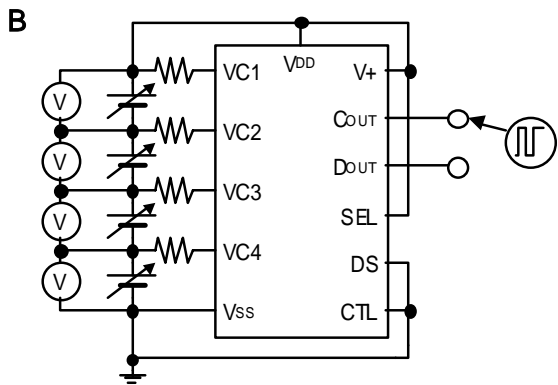
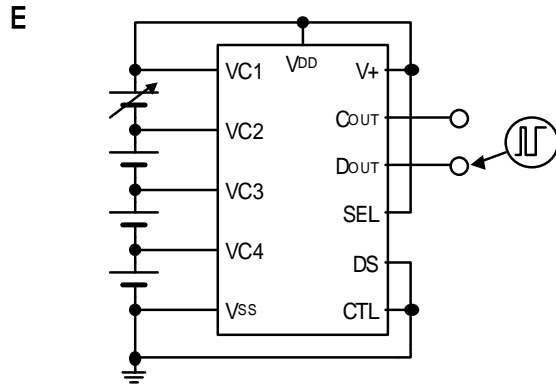
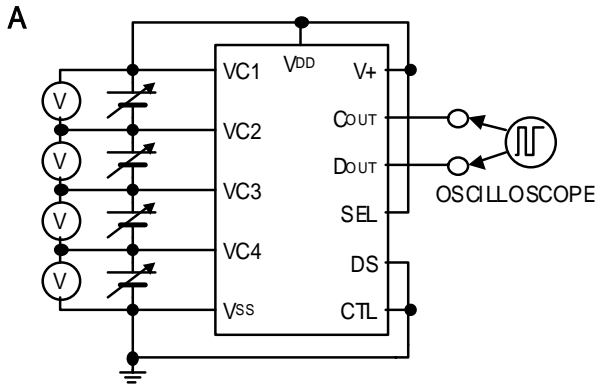
The typical application circuit diagram is just an example. This circuit performance largely depends on the PCB layout and external components. In the actual application, fully evaluation is necessary.

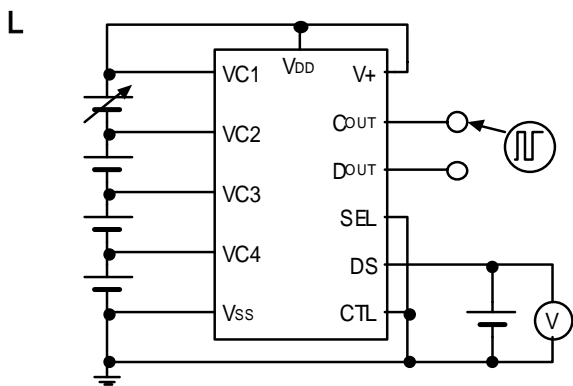
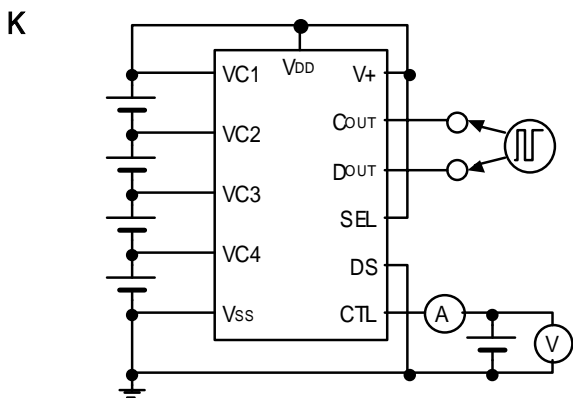
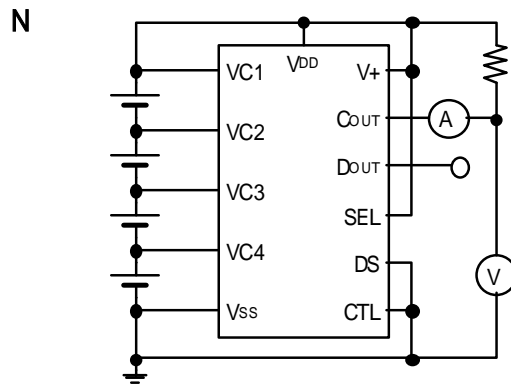
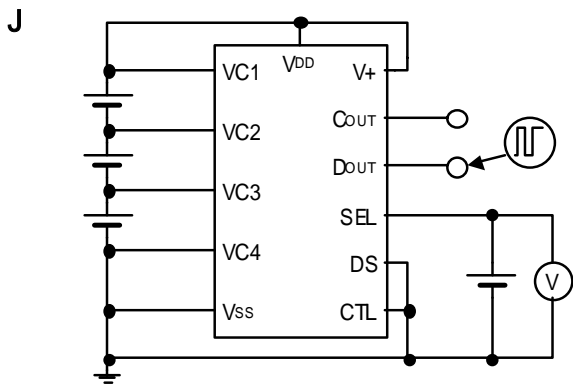
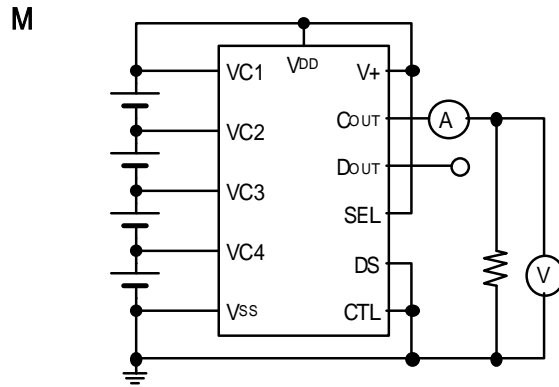
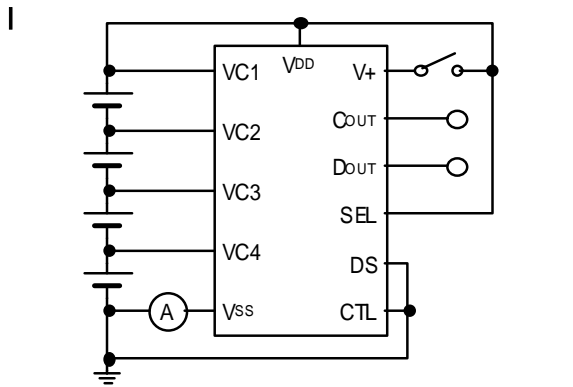
Over-voltage and the over current beyond the absolute maximum rating should not be forced to the protection IC and external components. If positive terminal and negative terminal of the battery pack short, even though the short protection circuit is built in the IC, during the delay time until detecting the short-circuit, a large current may flow through the FET.

Select an FET with large enough current capacity in order to endure the large current during the delay time.

Ricoh cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Ricoh product. If technical notes are not complied with the circuit which is used Ricoh product, Ricoh is not responsible for any damages and any accidents.

TEST CIRCUITS



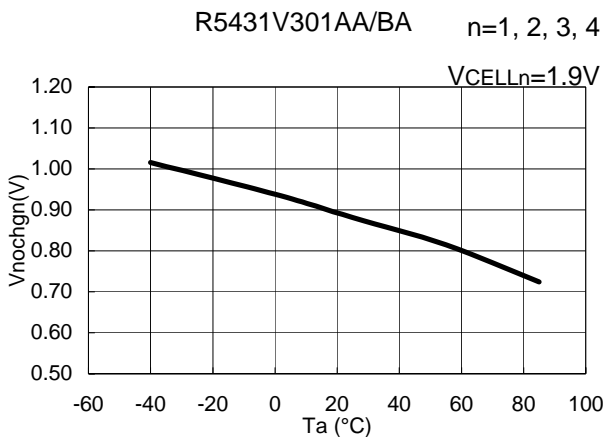


Typical Characteristics were obtained with using those above circuits:

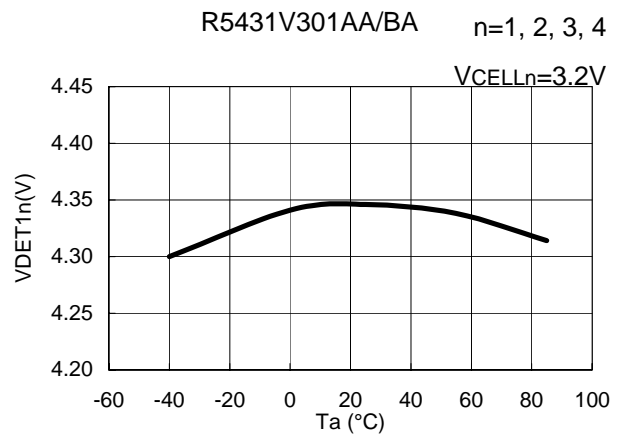
- Test Circuit A: Typical characteristics 1)
- Test Circuit B: Typical characteristics 2) 3)
- Test Circuit C: Typical characteristics 4) 5)
- Test Circuit D: Typical characteristics 6) 7)
- Test Circuit E: Typical characteristics 8) 9) 10)
- Test Circuit F: Typical characteristics 11) 12) 13) 14) 15) 16) 17) 18) 19)
- Test Circuit G: Typical characteristics 20)
- Test Circuit H: Typical characteristics 21) 22) 23)
- Test Circuit I: Typical characteristics 26)
- Test Circuit J: Typical characteristics 24)
- Test Circuit K: Typical characteristics 27)
- Test Circuit L: Typical characteristics 25)
- Test Circuit M: Typical characteristics 28)
- Test Circuit N: Typical characteristics 29) 30)

TYPICAL CHARACTERISTICS (Part 1)

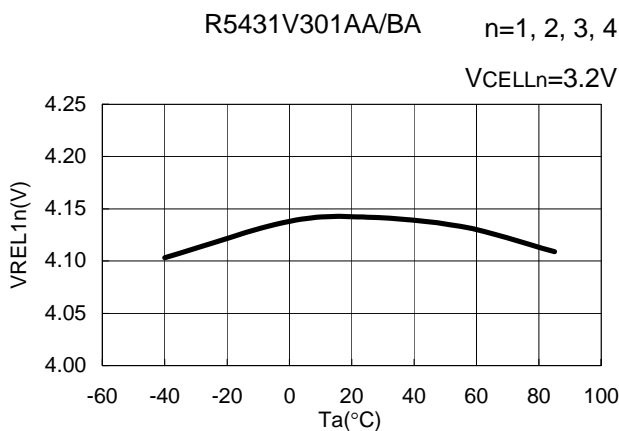
1) Maximum charge inhibit voltage for CELLn vs. Temperature



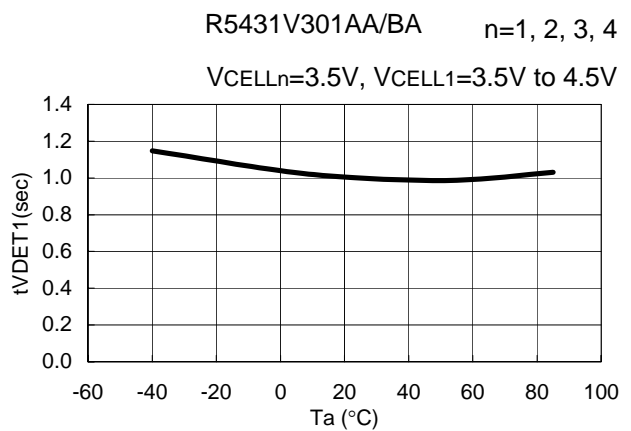
2) Over-charge voltage threshold (CELLn) vs. Temperature



3) CELLn Over-Charge Released Voltage vs. Temperature



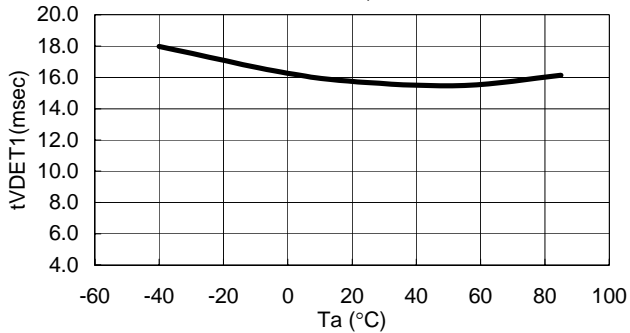
4) Over-charge Detector Delay Time vs. Temperature



5) Release from Over-charge Delay Time vs. Temperature

R5431V301AA/BA n=1, 2, 3, 4

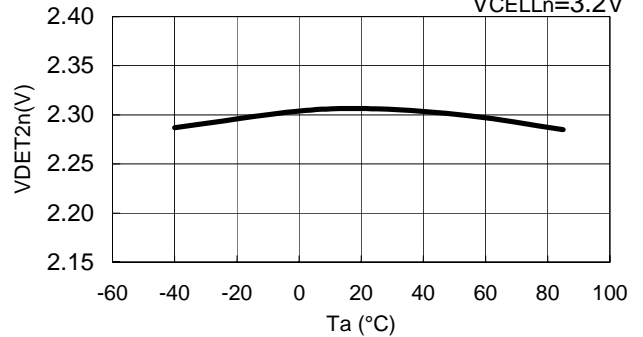
VCELLn=3.5V, VCELL1=4.5V to 3.5V



6) CELLn Over-discharge Detector Threshold vs. Temperature

R5431V301AA/BA n=1, 2, 3, 4

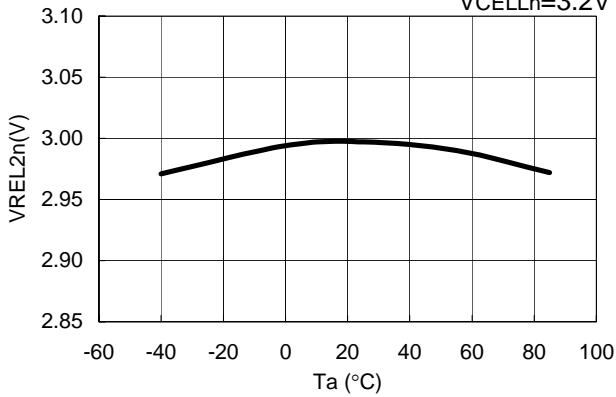
VCELLn=3.2V



7) CELLn Release Voltage from Over-discharge vs. Temperature

R5431V301AA/BA n=1, 2, 3, 4

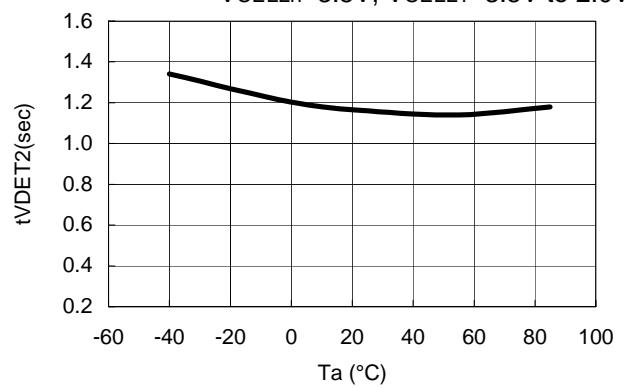
VCELLn=3.2V



8) Over-discharge Detector Delay Time vs. Temperature (Ver. AA)

R5431V301AA n=1, 2, 3, 4

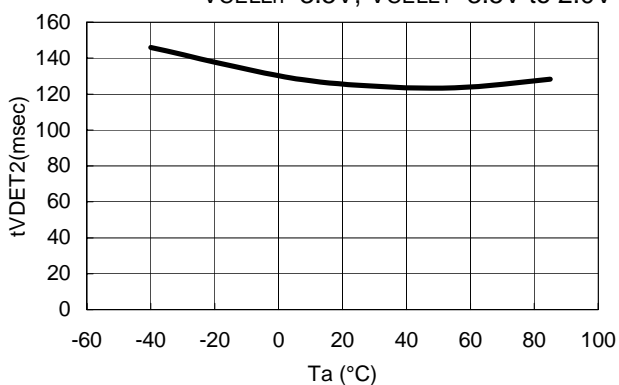
VCELLn=3.5V, VCELL1=3.5V to 2.0V



9) Output Delay Time of Over-discharge Detector vs. Temperature (Ver. BA)

R5431V301BA n=1, 2, 3, 4

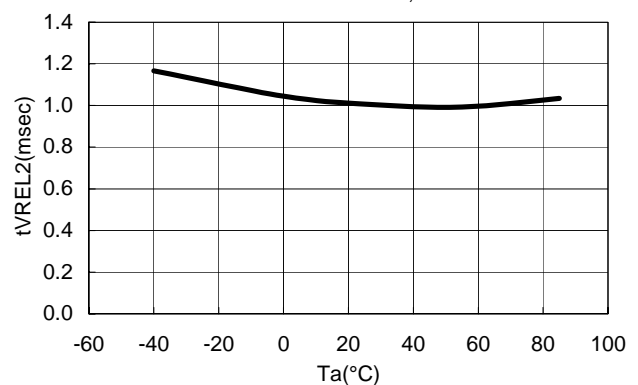
VCELLn=3.5V, VCELL1=3.5V to 2.0V



10) Output Delay Time of Release from Over-discharge vs. Temperature

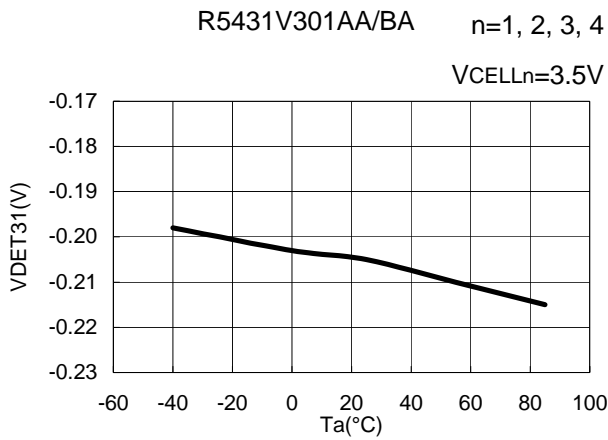
R5431V301AA/BA n=1, 2, 3, 4

VCELLn=3.5V, VCELL1=2.0V to 3.5V

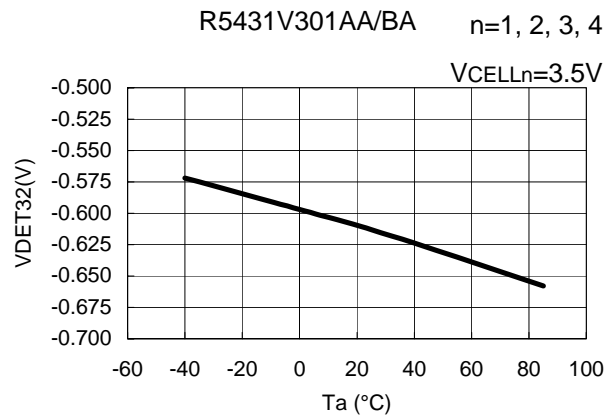


R5431Vxxxxx

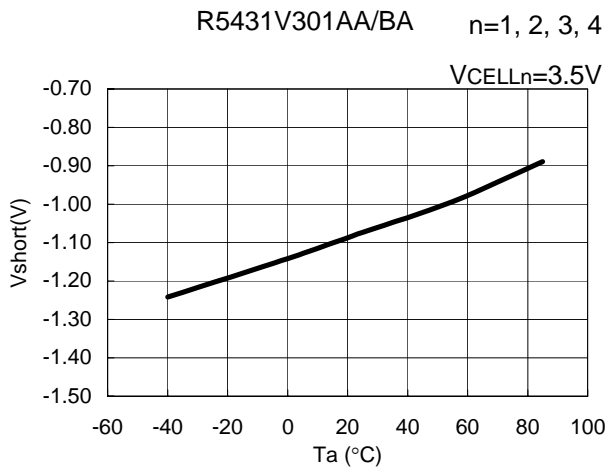
11) Excess Discharge Current Detector Threshold 1 vs. Temperature



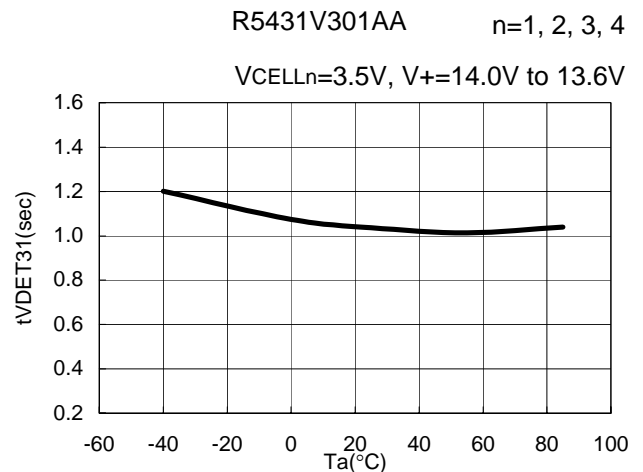
12) Excess Discharge Current Detector Threshold 2 vs. Temperature



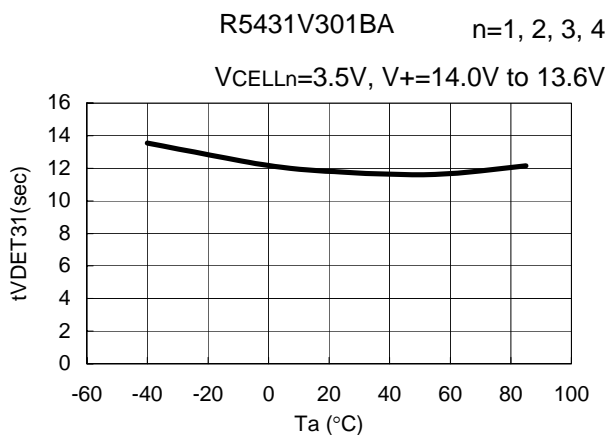
13) Short Detector Threshold vs. Temperature



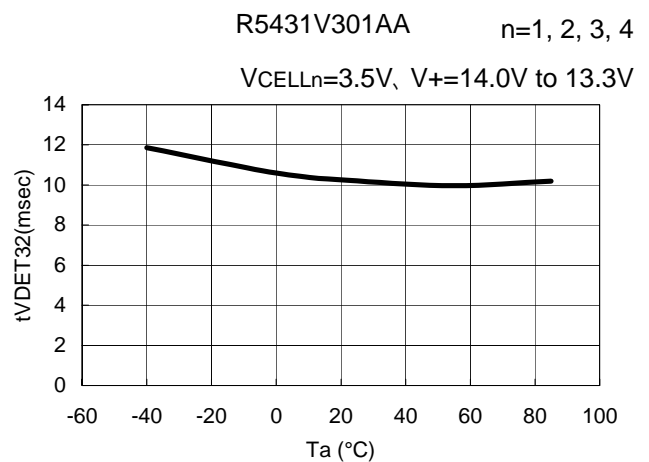
14) Output Delay Time of Excess discharge Current Detector 1 vs. Temperature (Ver. AA)



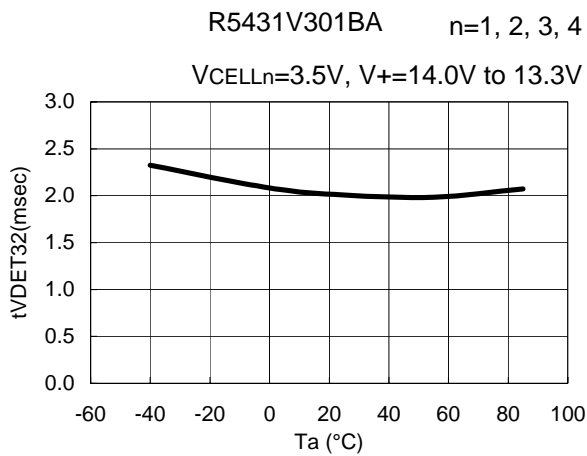
15) Output Delay Time of Excess discharge-current Detector 1 vs. Temperature (Ver. BA)



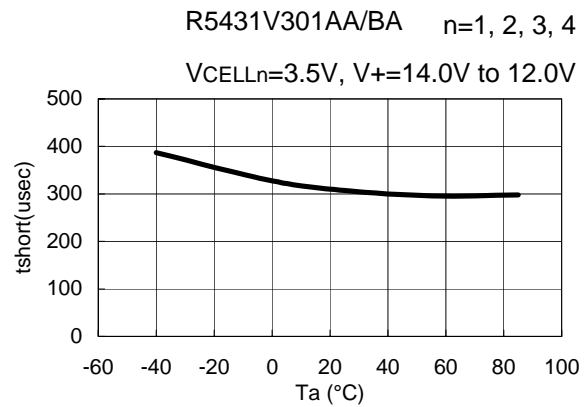
16) Output Delay Time of Excess Discharge Current Detector 2 vs. Temperature (Ver. AA)



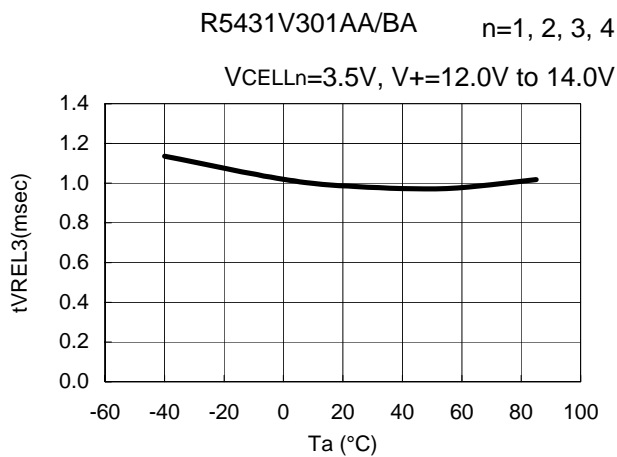
17) Output Delay Time of Excess Discharge Current Detector 2 vs. Temperature (Ver. BA)



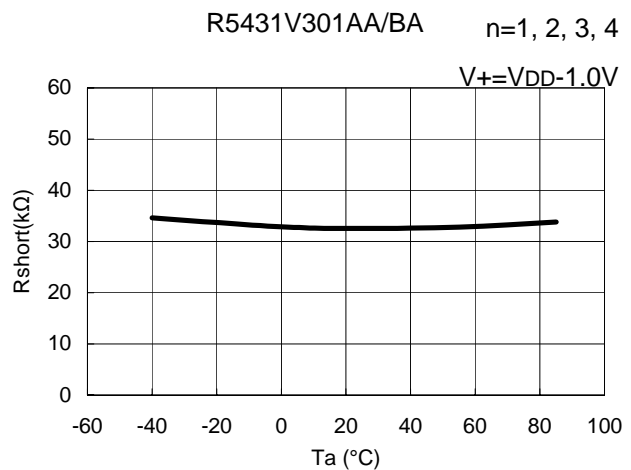
18) Output Delay Time of Short Detector vs. Temperature vs. Temperature



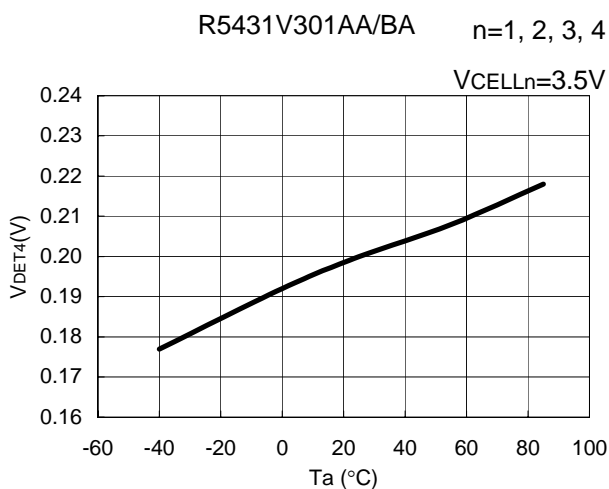
19) Output Delay Time for Release from Excess-discharge current vs. Temperature



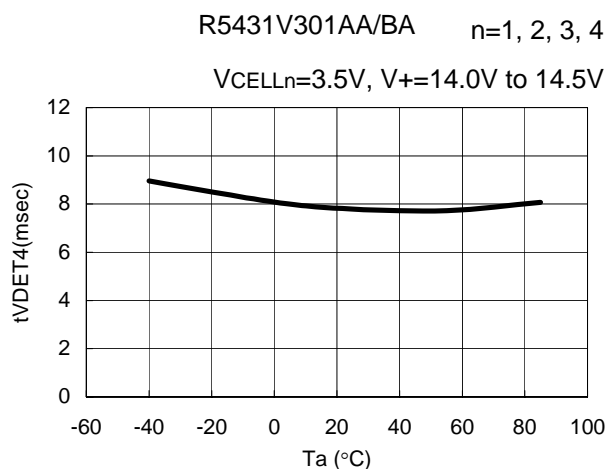
20) Excess Discharge Current Release Resistance vs. Temperature



21) Excess Charge Current Detector Threshold vs. Temperature

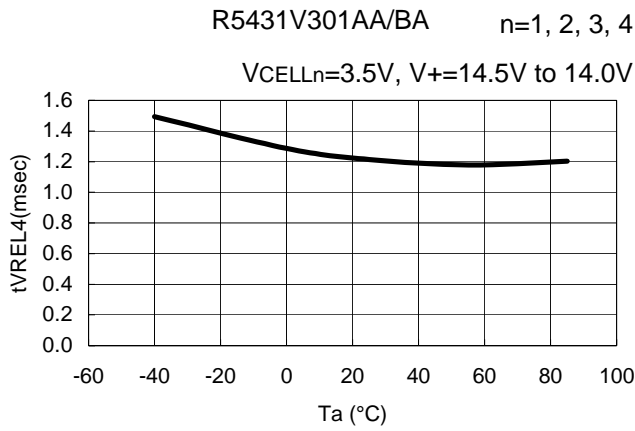


22) Output Delay Time of Excess Charge Current Detector vs. Temperature

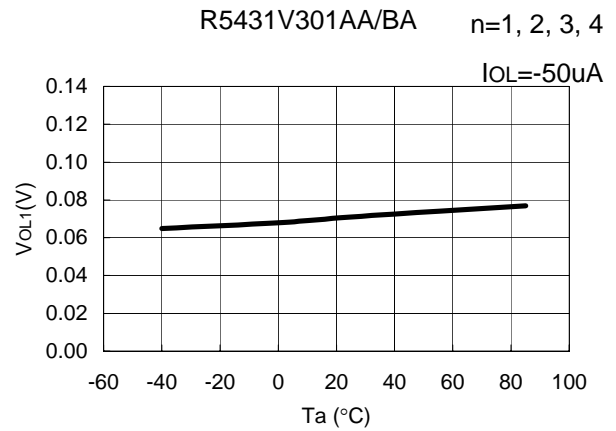


R5431Vxxxxx

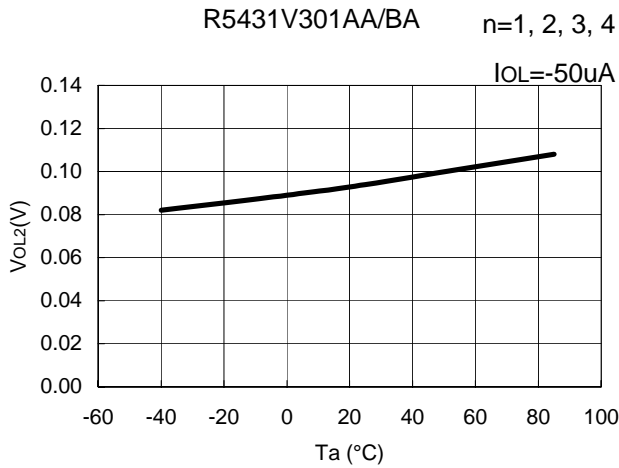
23) Output Delay Time of Release from Excess charge current vs. Temperature



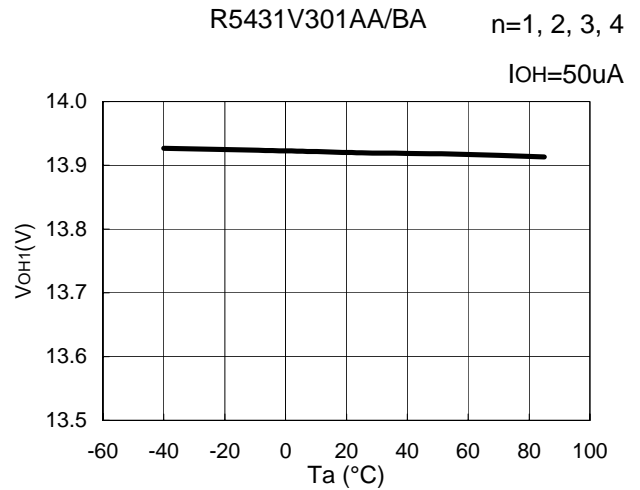
24) C_{OUT} Nch ON Voltage vs. Temperature



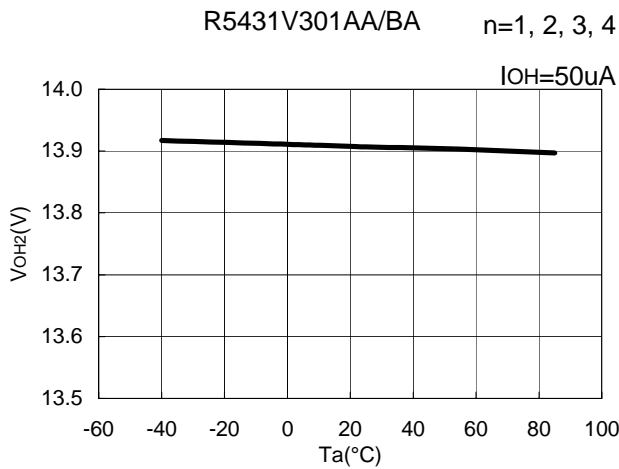
25) D_{OUT} Nch ON Voltage vs. Temperature



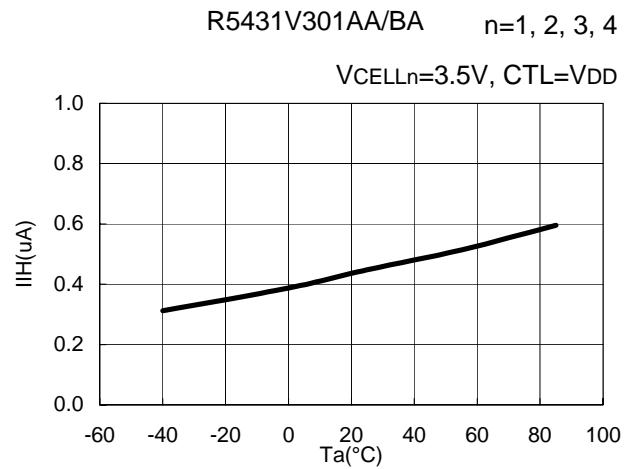
26) C_{OUT} Pch ON Voltage vs. Temperature



27) D_{OUT} Pch ON Voltage vs. Temperature



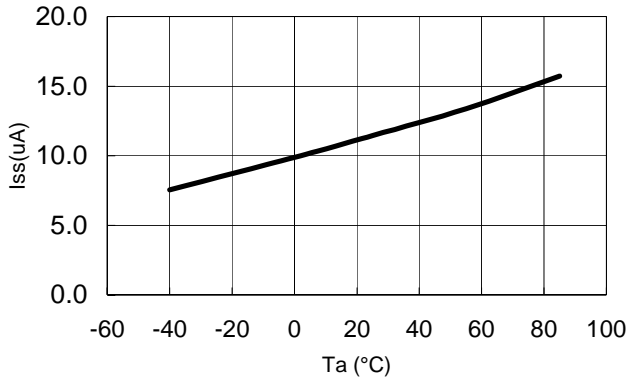
28) CTL pin "H" Input Current vs. Temperature



29) Supply Current (4-cell protection) vs. Temperature

R5431V301AA/BA n=1, 2, 3, 4

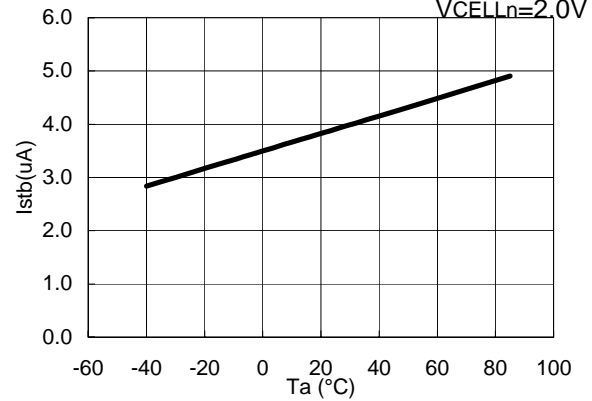
VCELLn=3.9V



30) Standby Current (4-cell protection) vs. Temperature

R5431V301AA/BA n=1, 2, 3, 4

VCELLn=2.0V

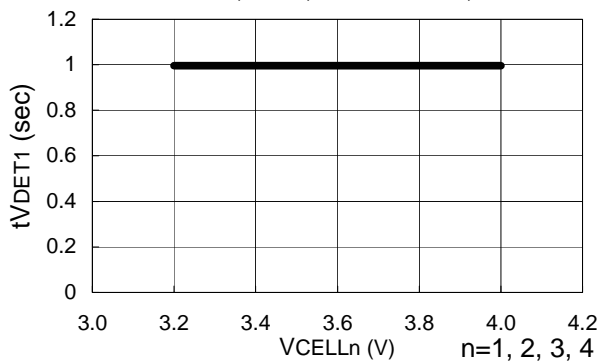


Part 2. Delay Time dependence on VDD

1) Delay Time for Over-charge detector vs. VDD

R5431V301AA/BA

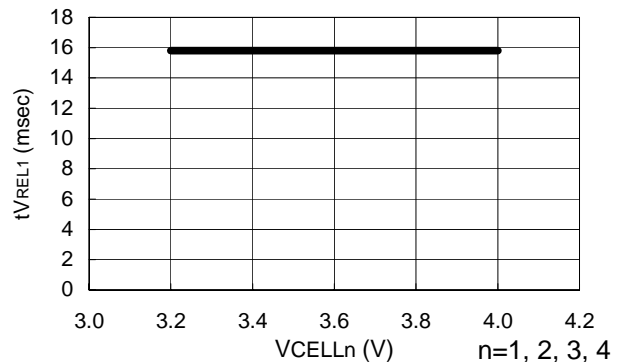
VCELL1=3.2V, 3.6V, 4.0V to 4.5V, SEL=VDD



2) Delay Time for Release from Over-charge vs. VDD

R5431V301AA/BA

VCELL1=3.2V, 3.6V, 4.0V to 4.5V, SEL=VDD

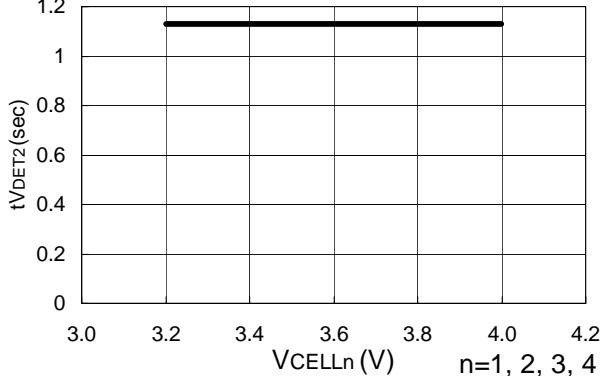


3) Output Delay of Over-discharge Detector vs. VDD

(Ver. AA)

R5431V301AA

VCELL1=3.2V, 3.6V, 4.0V to 2.0V, SEL=VDD

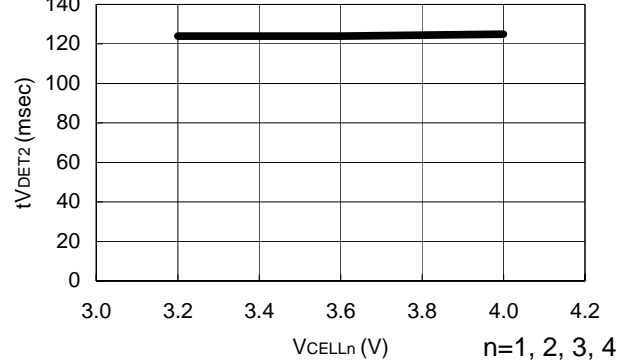


4) Output Delay of Over-discharge Detector vs. VDD

(Ver. BA)

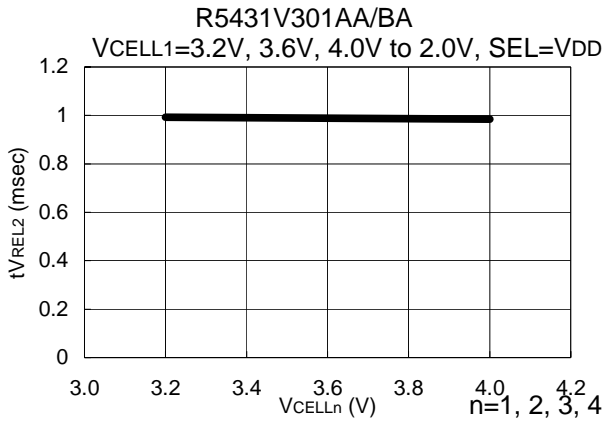
R5431V301BA

VCELL1=3.2V, 3.6V, 4.0V to 2.0V, SEL=VDD

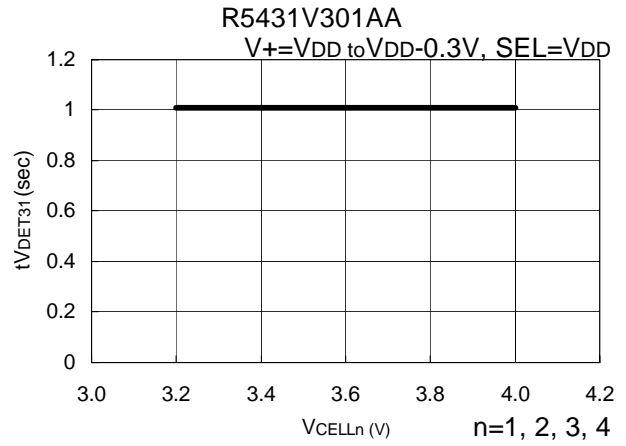


R5431Vxxxxx

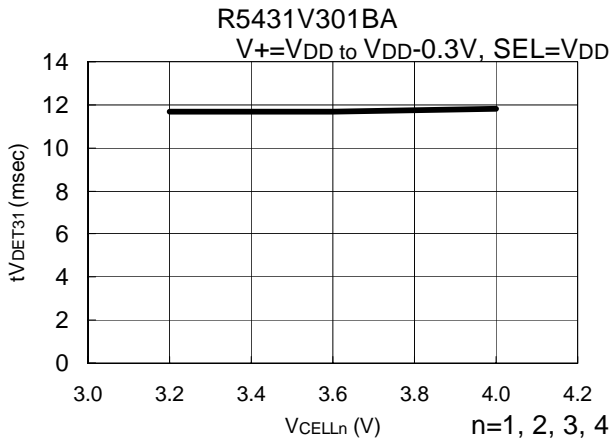
5) Output Delay of Release from Excess Discharge Current vs. V_{DD}



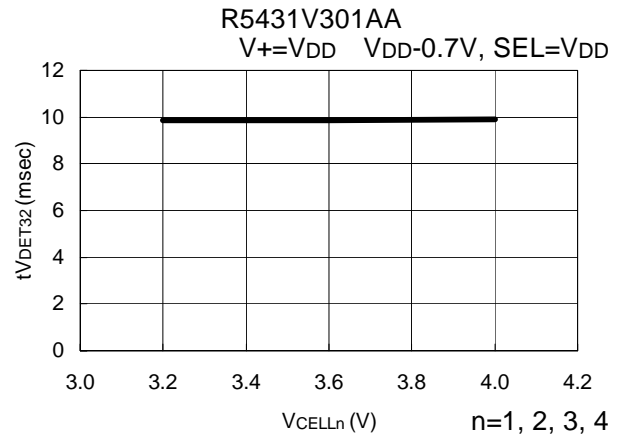
6) Output Delay of Excess Discharge Current 1 vs. V_{DD}



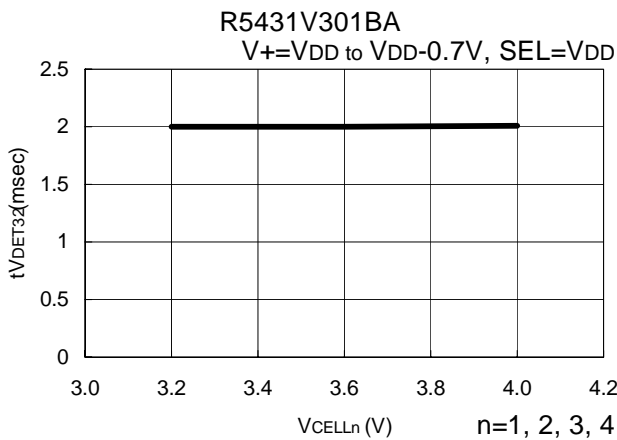
7) Delay Time of Excess Discharge Current Detector 1 vs. V_{DD} (Ver. BA)



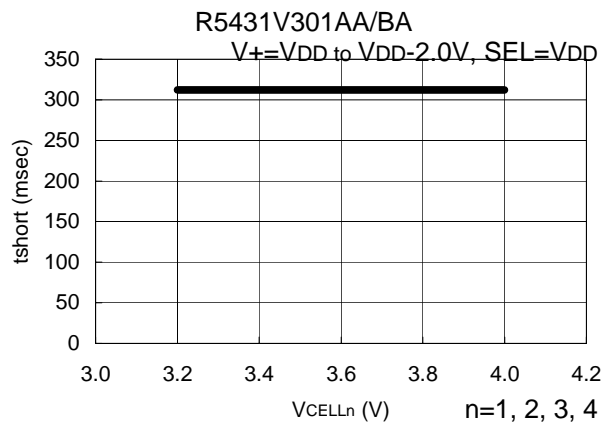
8) Delay Time of Excess Discharge Current Detector 2 vs. V_{DD} (Ver. AA)



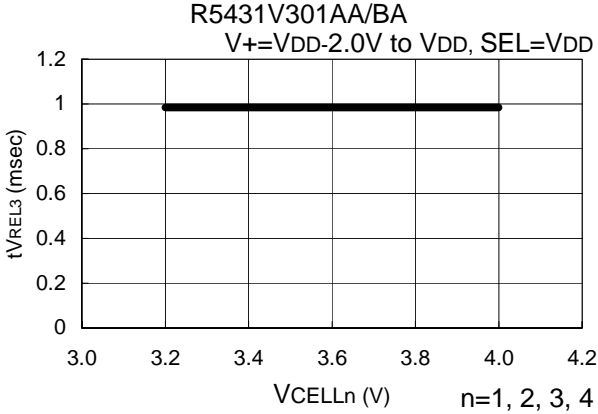
9) Delay Time of Excess Discharge Current Detector 2 vs. V_{DD} (Ver. BA)



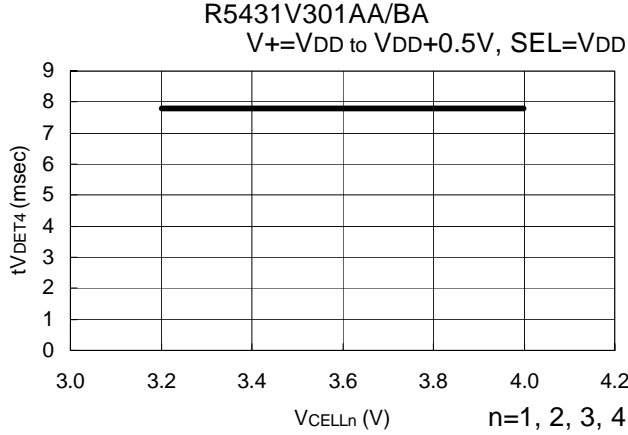
10) Delay Time of Short Detector vs. V_{DD}



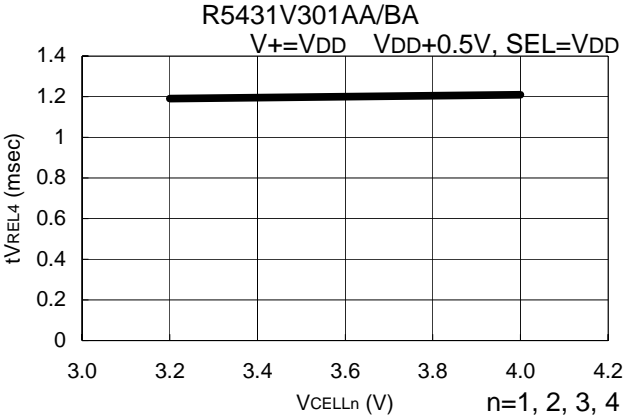
11) Delay Time of Release from Excess discharge current vs. VDD



12) Delay Time of Excess Charge Current Detector vs. VDD

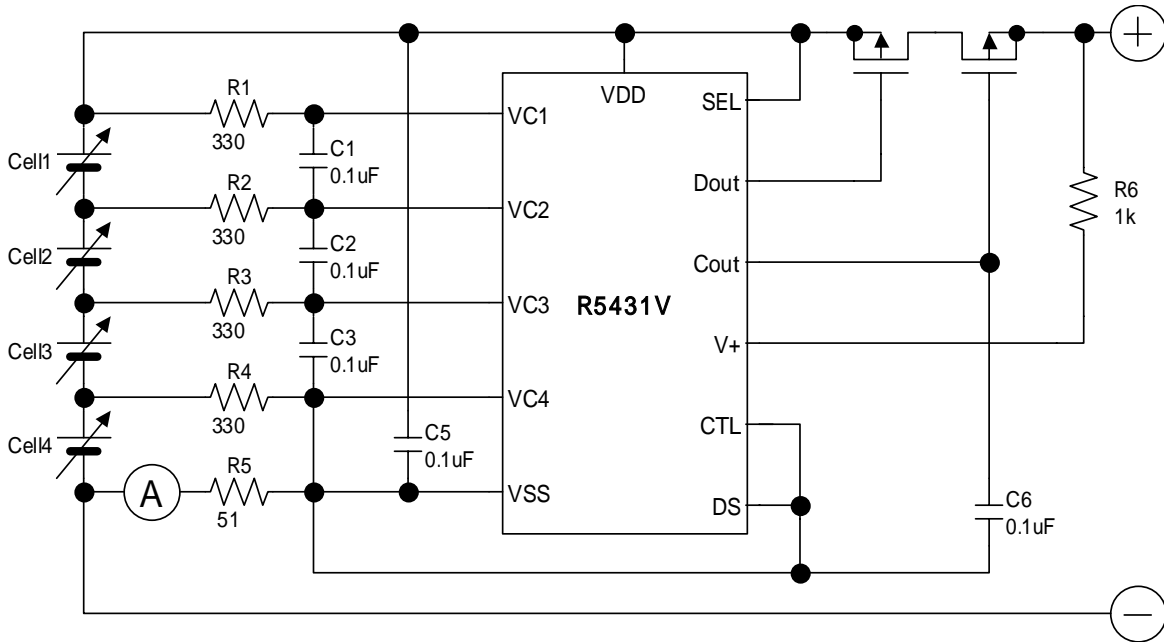


13) Delay Time of Release from Excess Charge Current vs. VDD

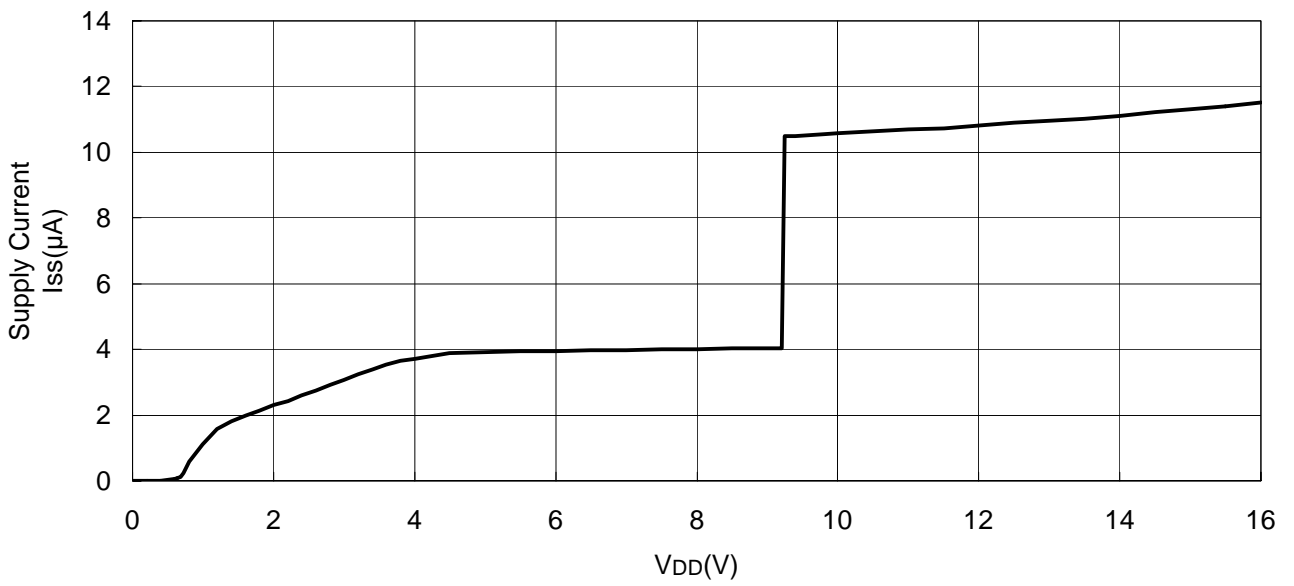


Part 3 Supply Current dependence on V_{DD}

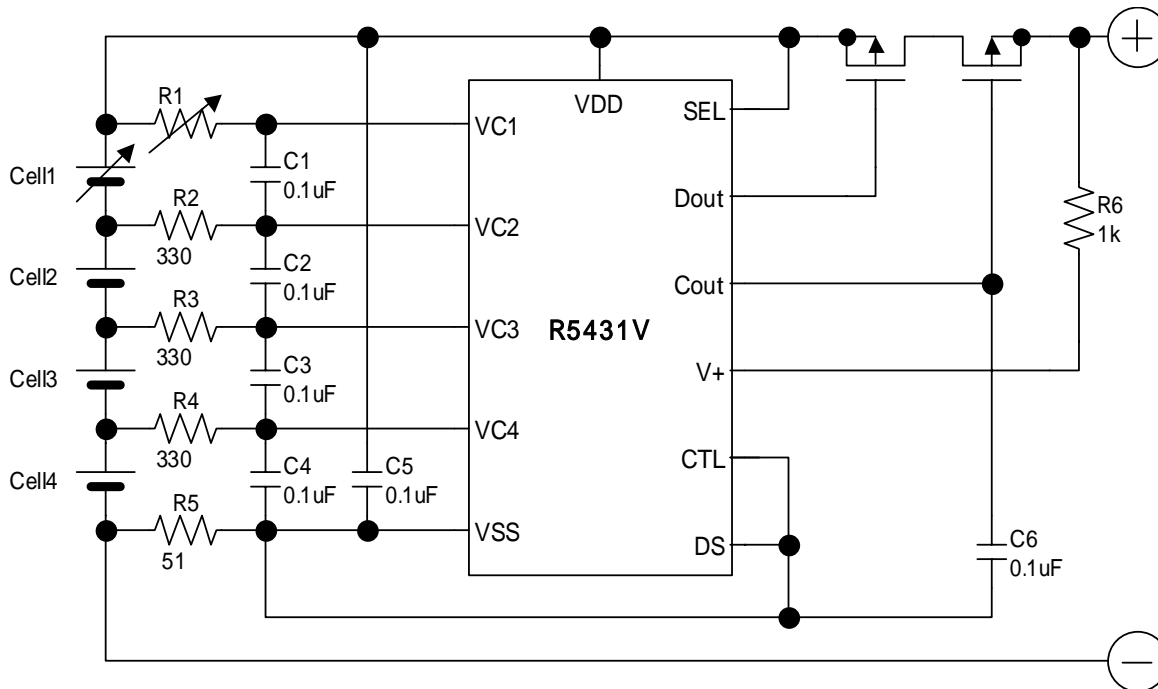
Test Circuit (for 4-cell protection)



4-cell protection Supply Current vs. V_{DD}

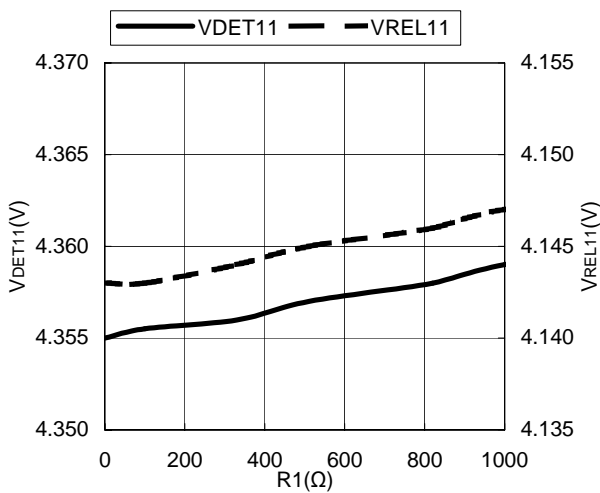


Part 4 Over-charge detector, Release voltage from Over-charge, Over-discharge detector, Release voltage from Over-discharge dependence on External Resistance value

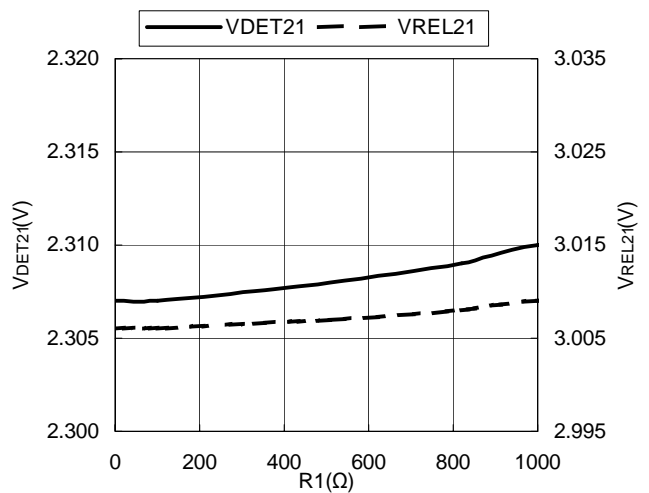


Test Circuit

Over-charge Detector Threshold / Released Voltage from Over-charge vs. R1 (CELL1)



Over-discharge / Released from Over-discharge Threshold vs. R1 (CELL1)





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RICOH RICOH ELECTRONIC DEVICES CO., LTD.

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Sales & Support Offices

RICOH ELECTRONIC DEVICES CO., LTD.

Higashi-Shinagawa Office (International Sales)
3-32-3, Higashi-Shinagawa, Shinagawa-ku, Tokyo 140-8655, Japan
Phone: +81-3-5479-2857 Fax: +81-3-5479-0502

RICOH EUROPE (NETHERLANDS) B.V.

Semiconductor Support Centre
Prof. W.H. Keesomlaan 1, 1183 DJ Amstelveen, The Netherlands
Phone: +31-20-5474-309

RICOH INTERNATIONAL B.V. - German Branch

Semiconductor Sales and Support Centre
Oberrather Strasse 6, 40472 Düsseldorf, Germany
Phone: +49-211-6546-0

RICOH ELECTRONIC DEVICES KOREA CO., LTD.

3F, Haesung Bldg, 504, Teheran-ro, Gangnam-gu, Seoul, 135-725, Korea
Phone: +82-2-2135-5700 Fax: +82-2-2051-5713

RICOH ELECTRONIC DEVICES SHANGHAI CO., LTD.

Room 403, No.2 Building, No.690 Bibo Road, Pu Dong New District, Shanghai 201203, People's Republic of China
Phone: +86-21-5027-3200 Fax: +86-21-5027-3299

RICOH ELECTRONIC DEVICES CO., LTD.

Taipei office
Room 109, 10F-1, No.51, Hengyang Rd., Taipei City, Taiwan (R.O.C.)
Phone: +886-2-2313-1621/1622 Fax: +886-2-2313-1623